

# The X-Factor - How X-ray Technology is Improving the Electronics Assembly Industry



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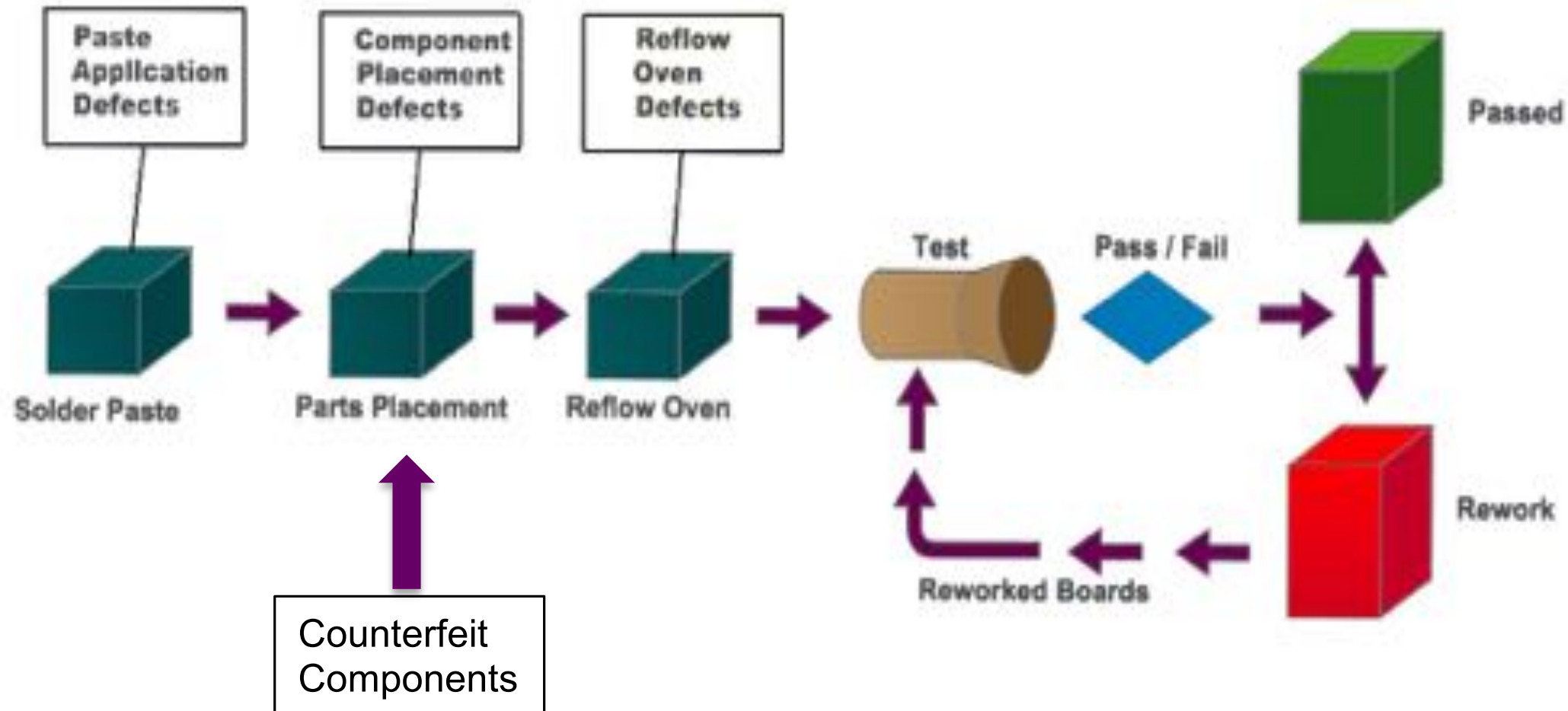
[bcardoso@creativeelectron.com](mailto:bcardoso@creativeelectron.com)



# Summary for today

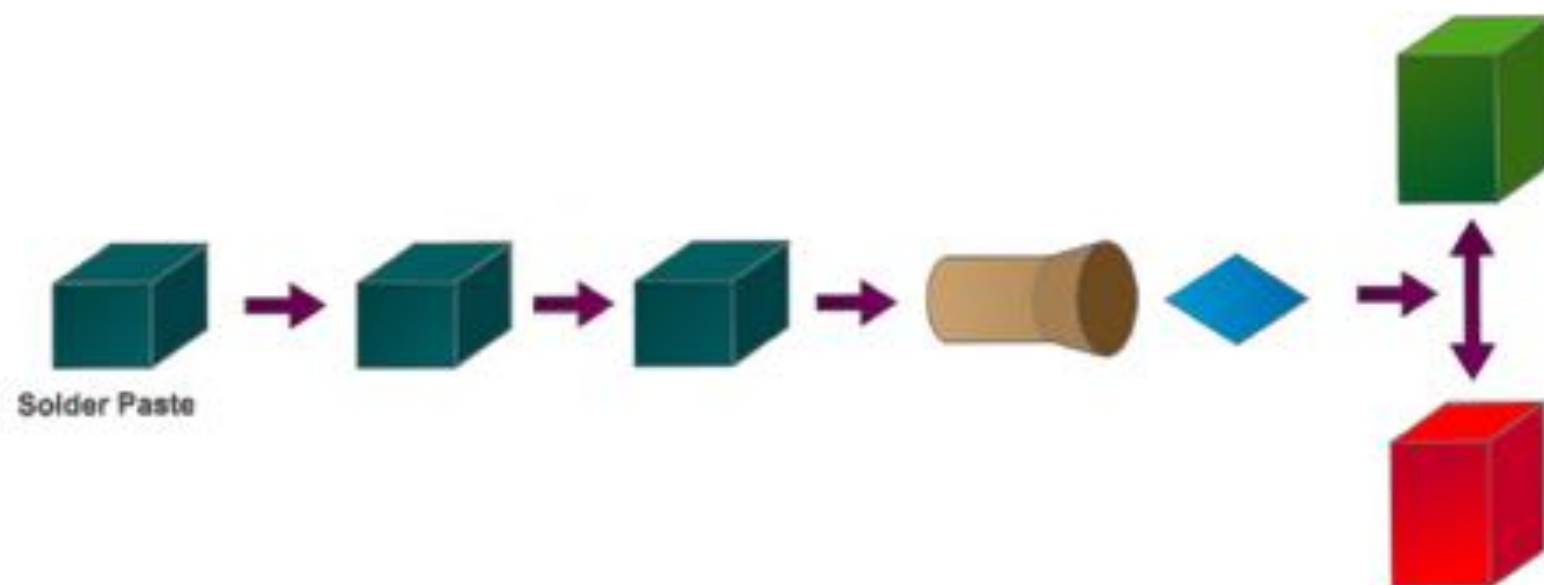
1. Electronic component inspection and failure analysis.
2. Component counting and material management.
3. Reverse engineering.
4. *Counterfeit detection.*
5. Real-time defect verification.
6. Computed tomography (CT) techniques and how to differentiate between 2D, 2.5D, and 3D x-ray inspection.
7. Design for manufacturing (DFM) and design for x-ray inspection (DFXI).
8. Voids, bridging, and head-in-pillow failures in bottom terminated components (BTC).
9. Artificial Intelligence and x-ray inspection

# Where Are Defects Introduced?



# Solder Paste Application Defects

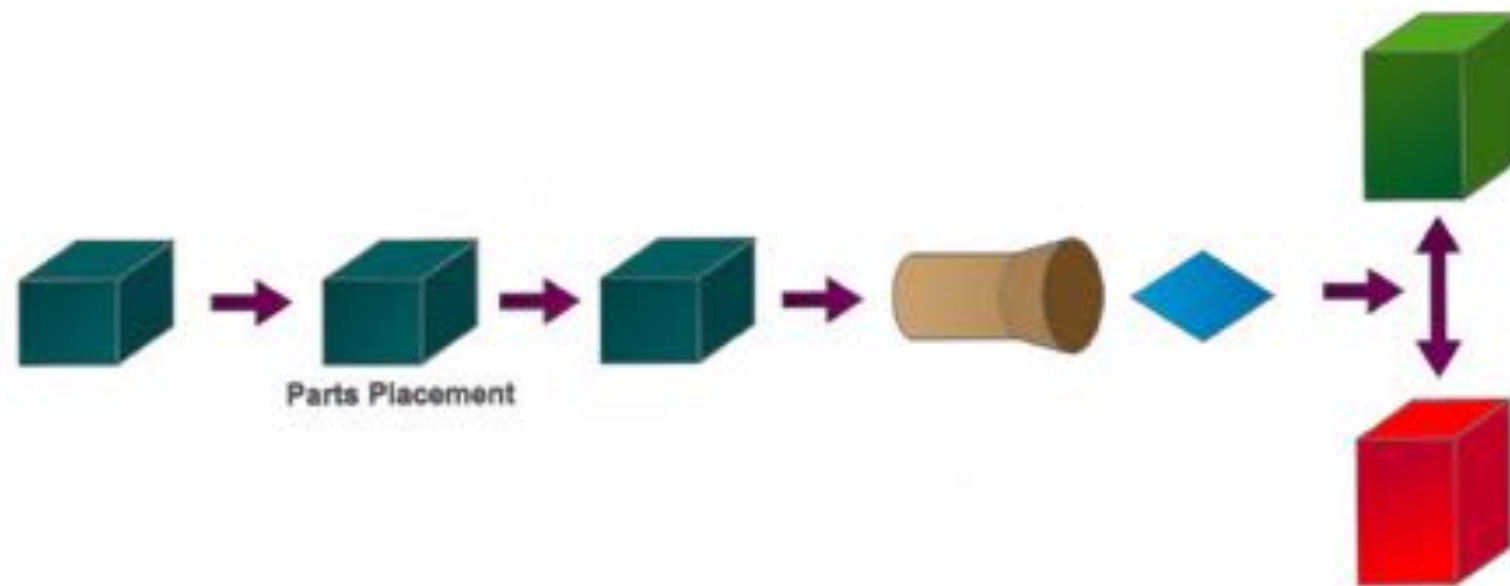
- \* Defects associated with paste application
  - \* Excess solder
  - \* Solder bridges
  - \* Insufficient solder





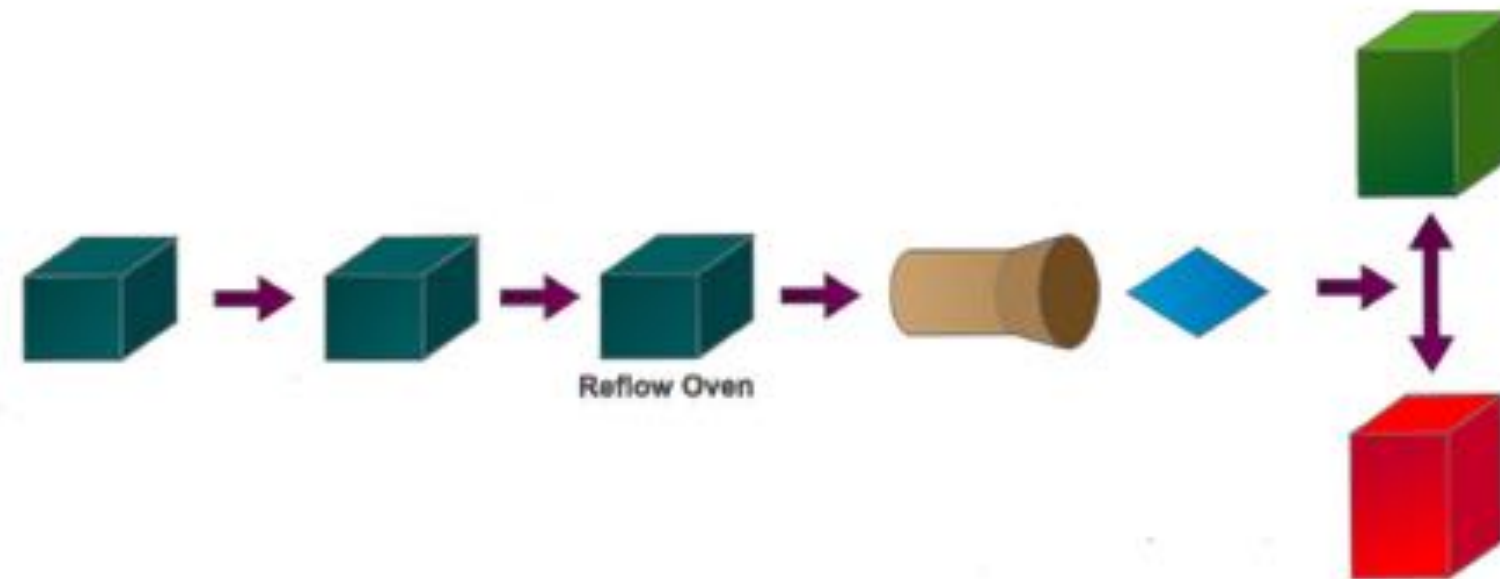
# Component Placement Defects

- \* Defects associated with component placement
  - \* Misalignment
  - \* Polarity
  - \* Missing component



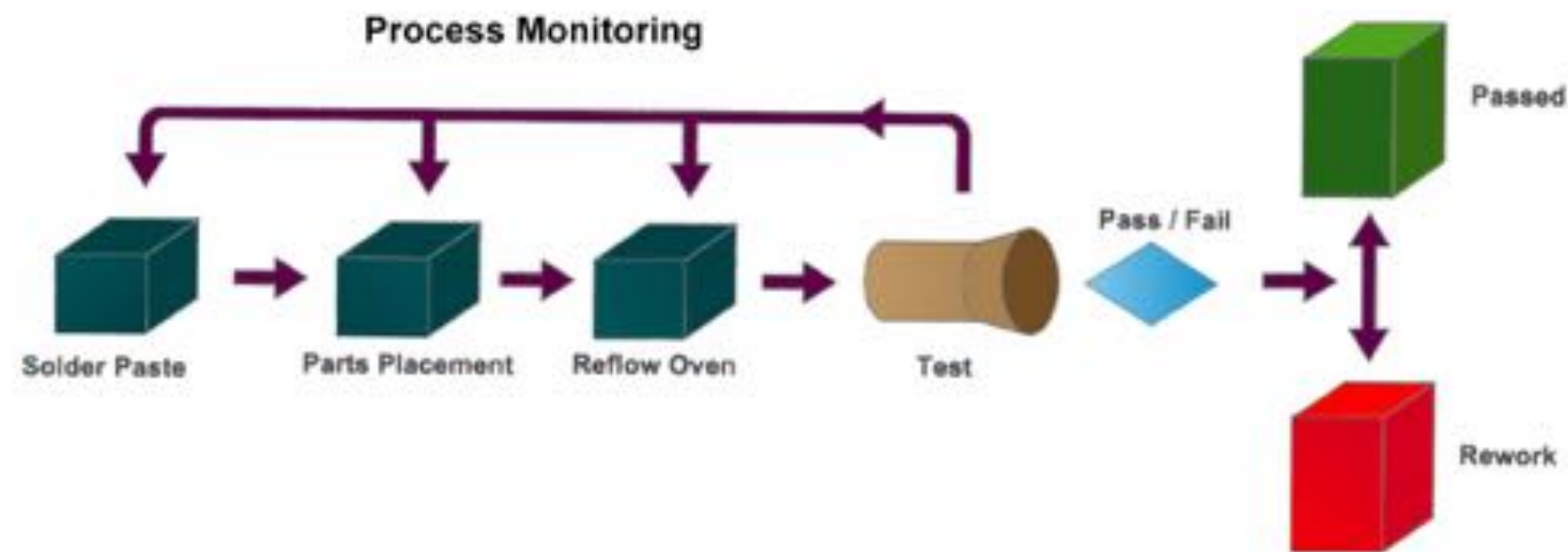
# Reflow Oven Defects

- \* Defects associated with the reflow profile
  - \* Voiding
  - \* Bridging
  - \* Solder balls
  - \* Excess solder
  - \* Insufficient solder

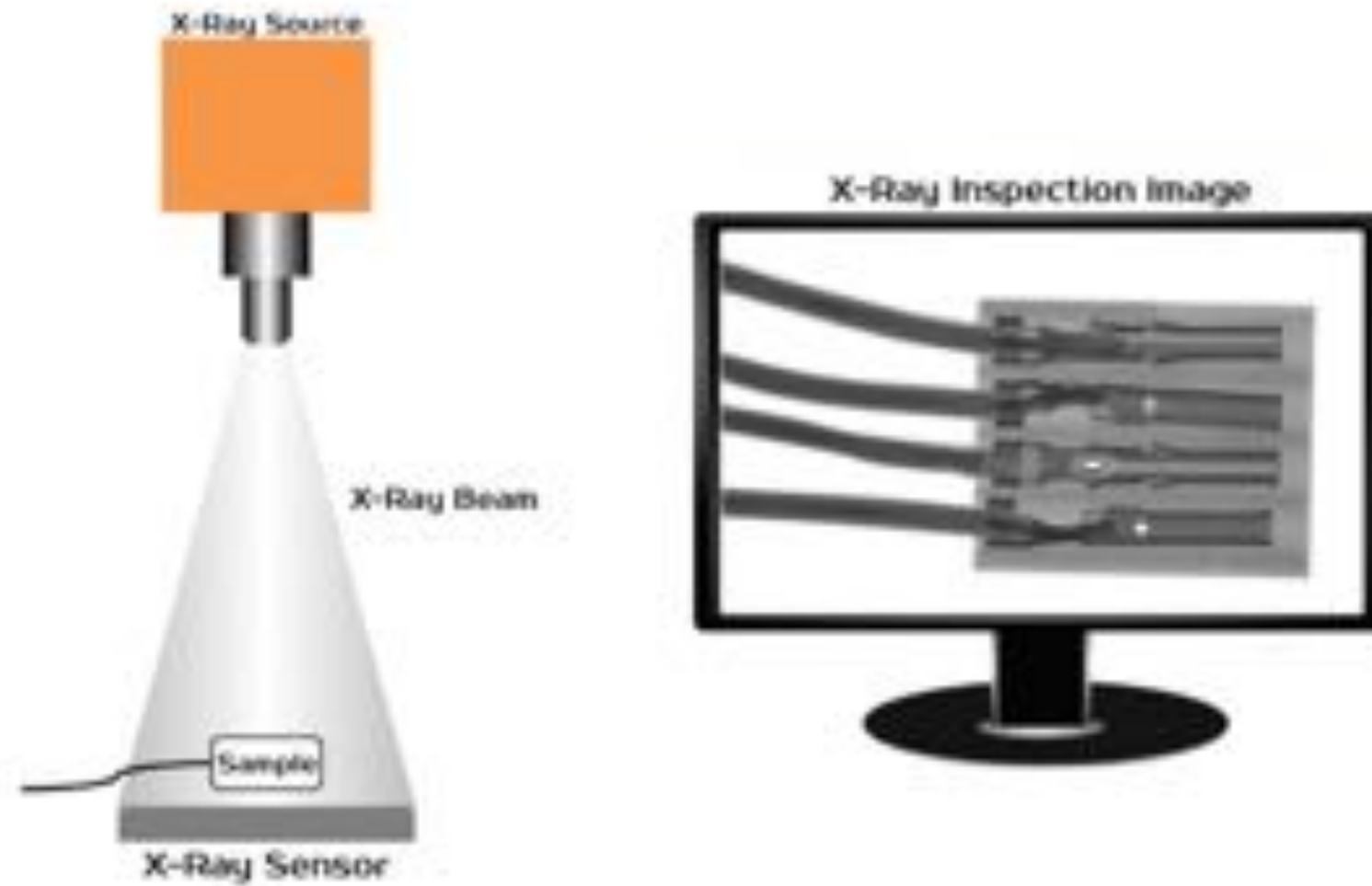


# Statistical Process Control

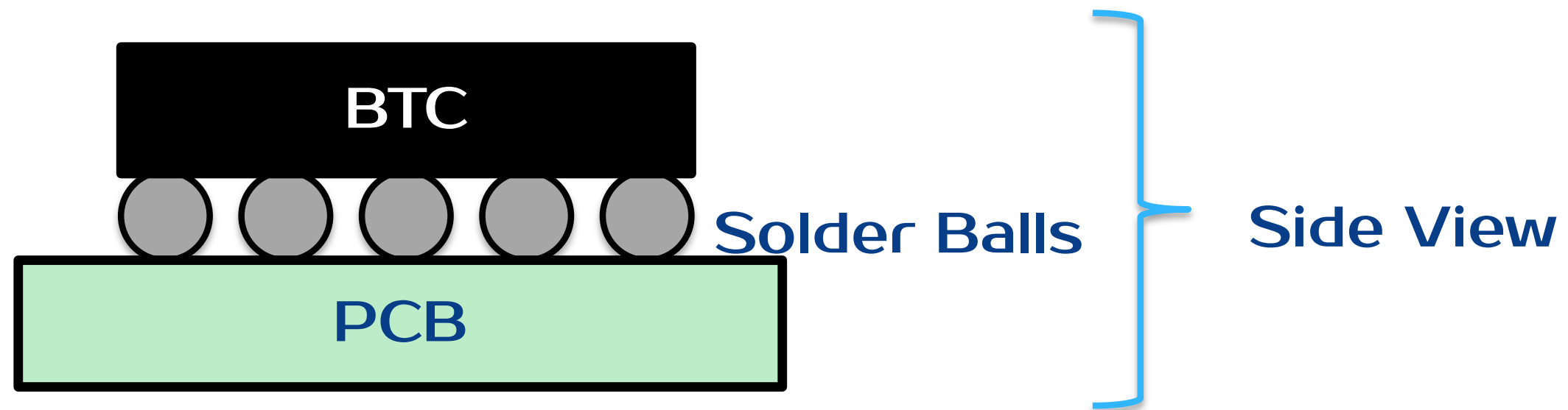
- ✱ Manufacturing process quality assurance.
  - ✱ Solder joint measurement data, collected during x-ray test, can be statistically analyzed to identify manufacturing drifts, trends and other relevant



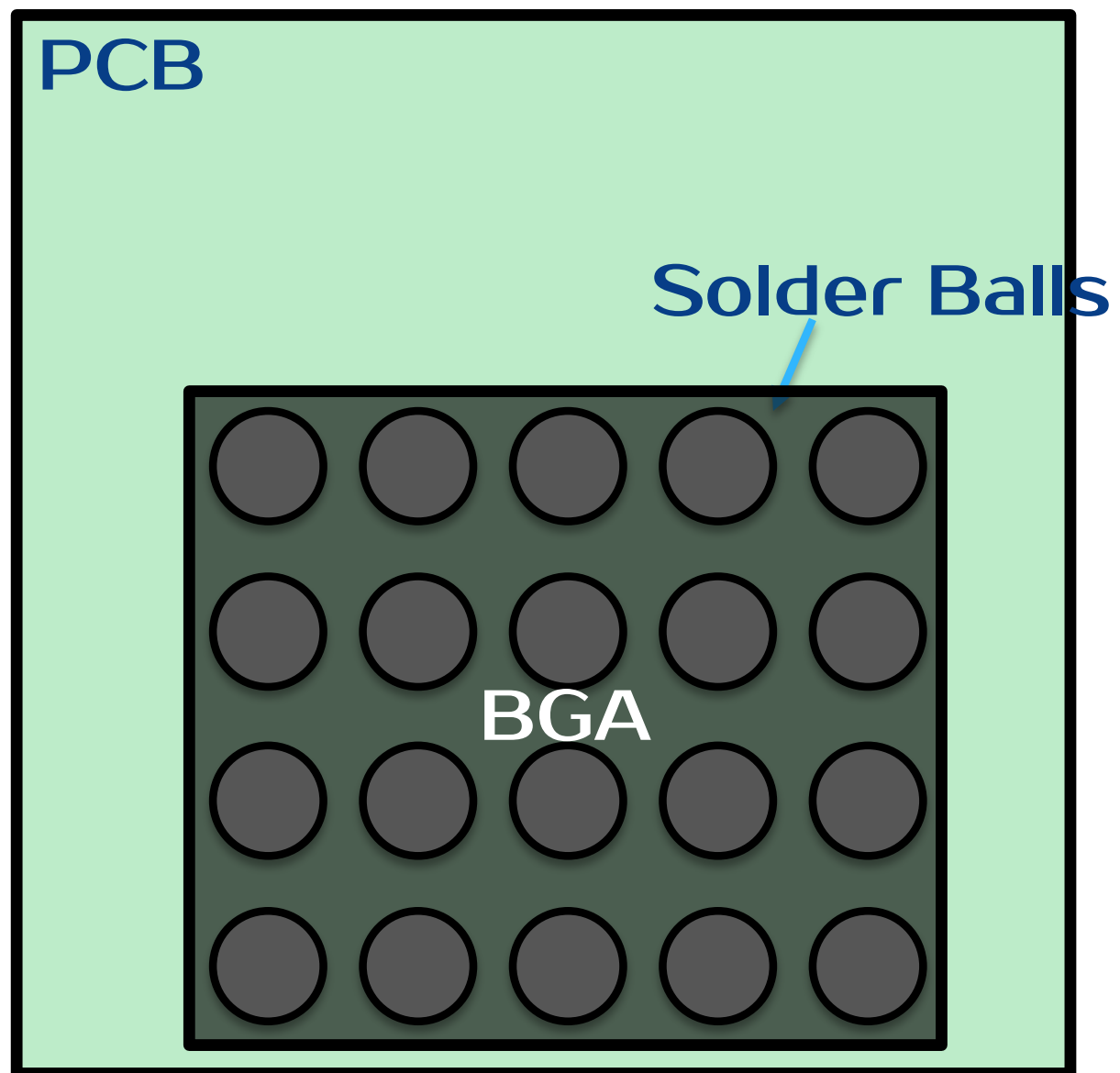
# Principles of x-ray inspection



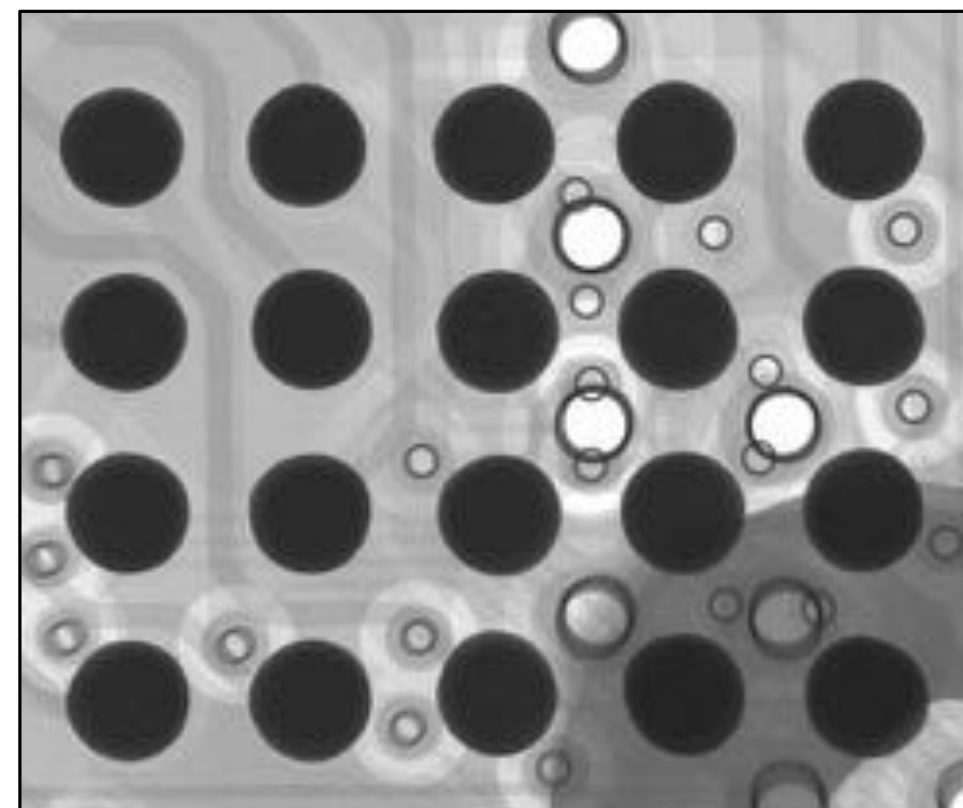
# X-ray imaging 101: the bottom terminated component, side view



# X-ray imaging 101: the BGA, top view



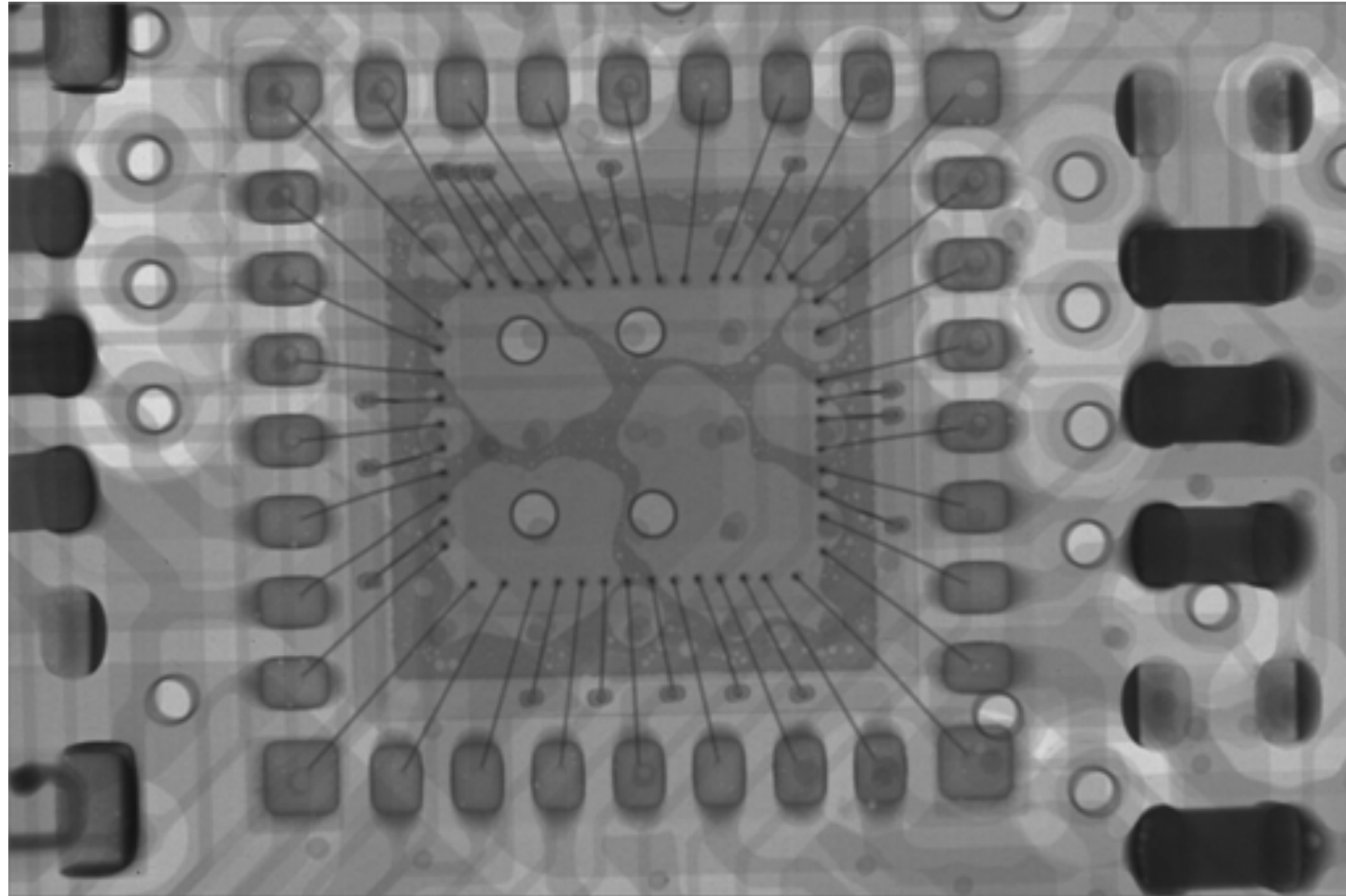
## X-ray image of BGA



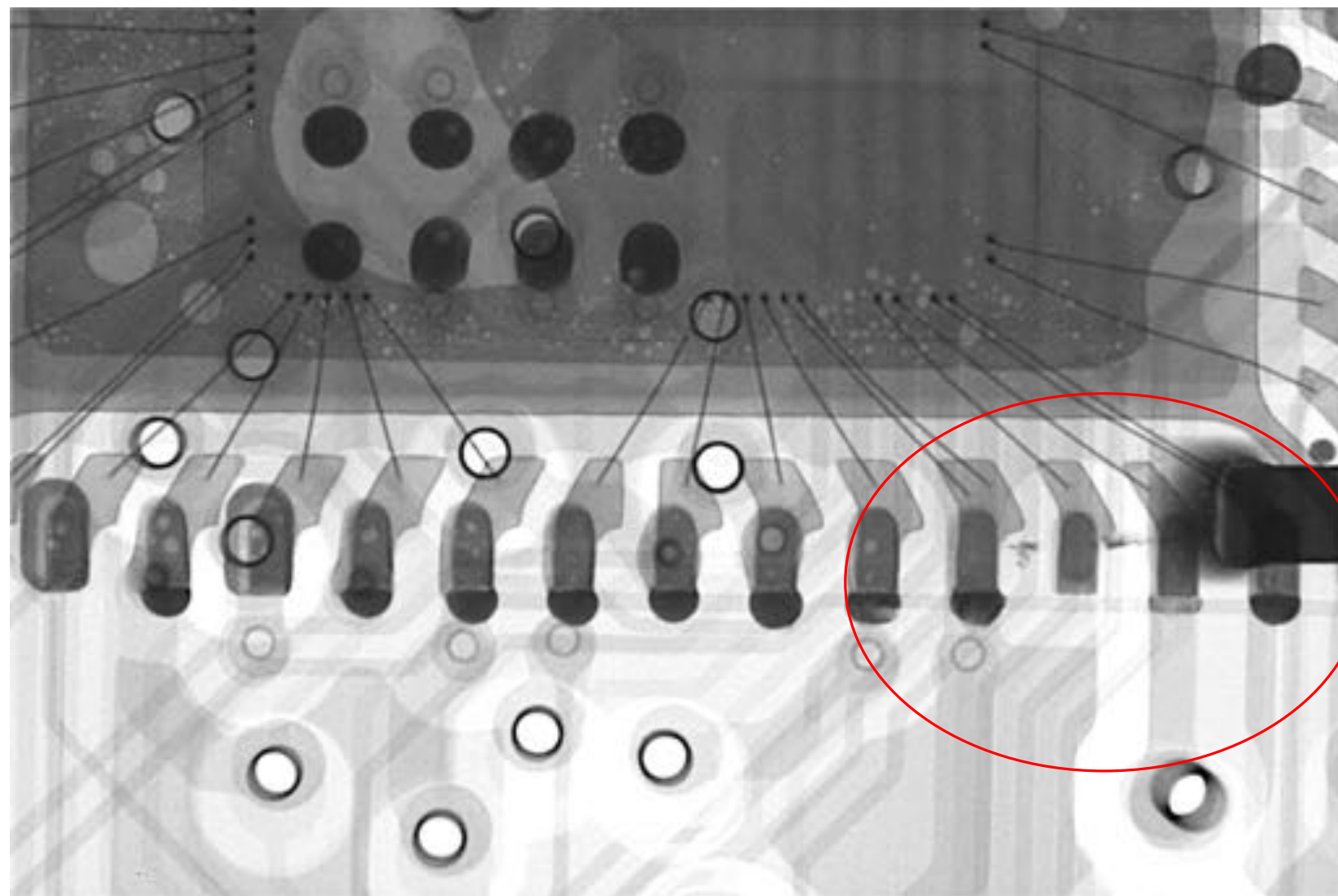




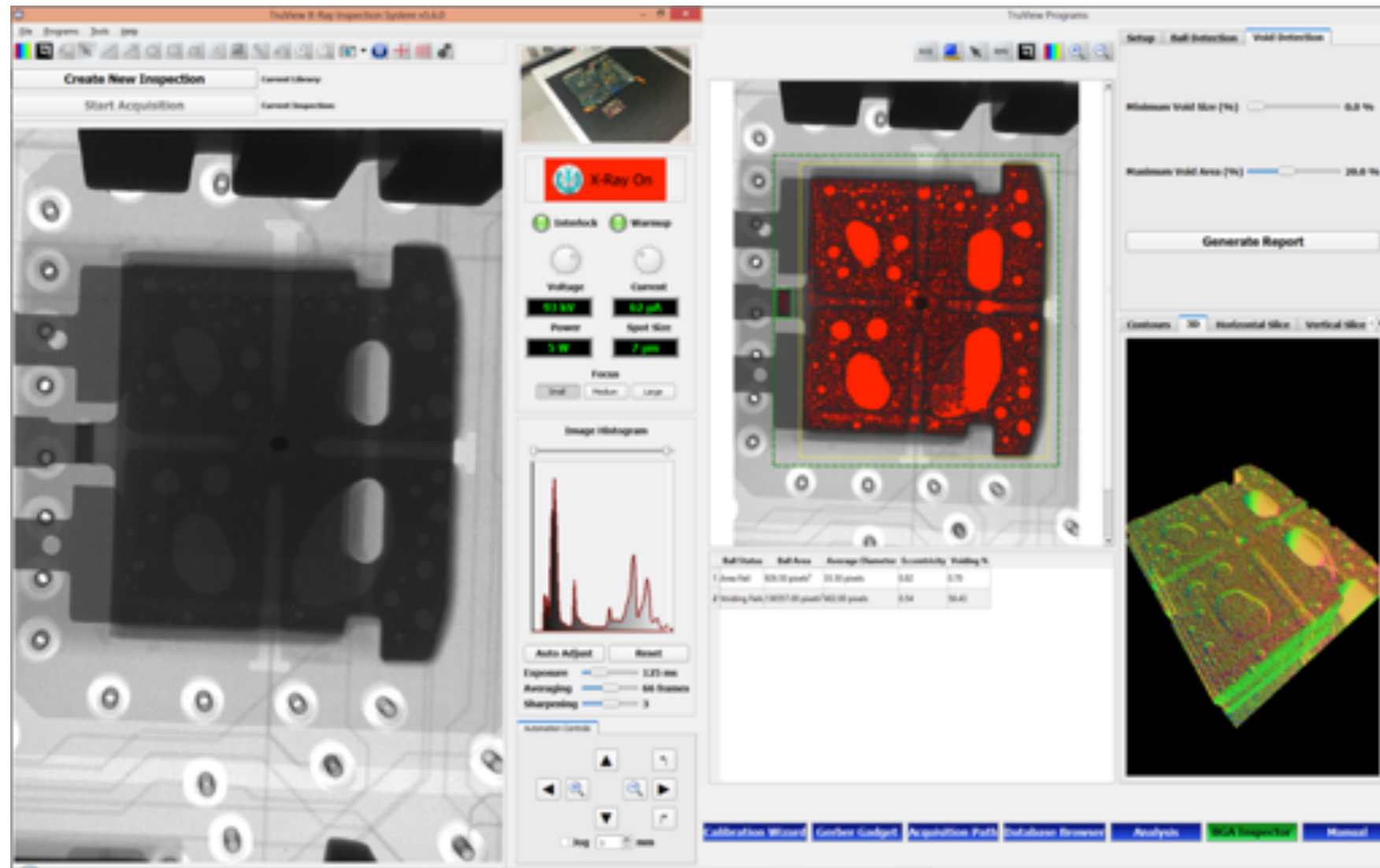
# QFN assembly with excess voiding



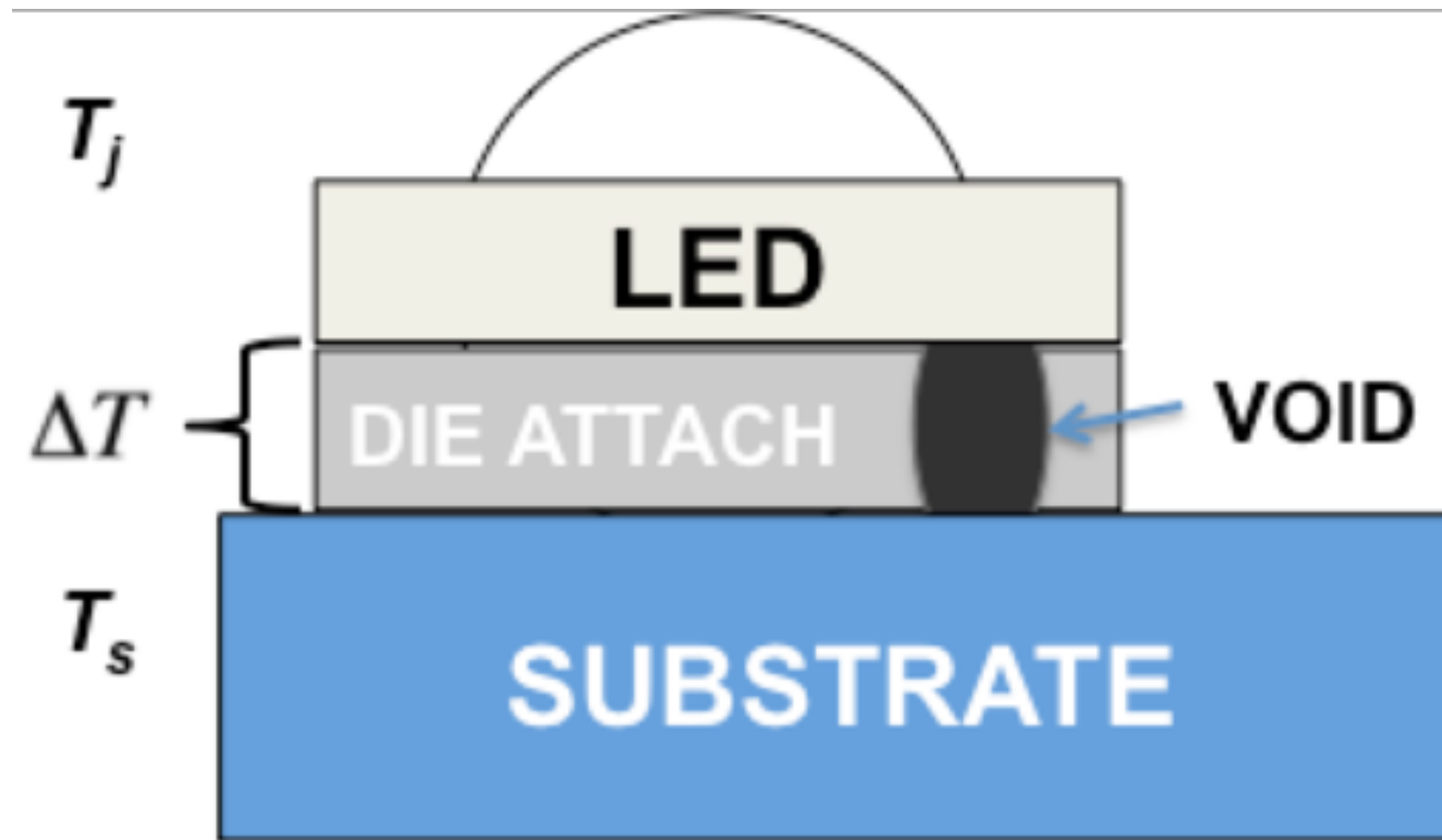
# Detail of open pin in QFN package



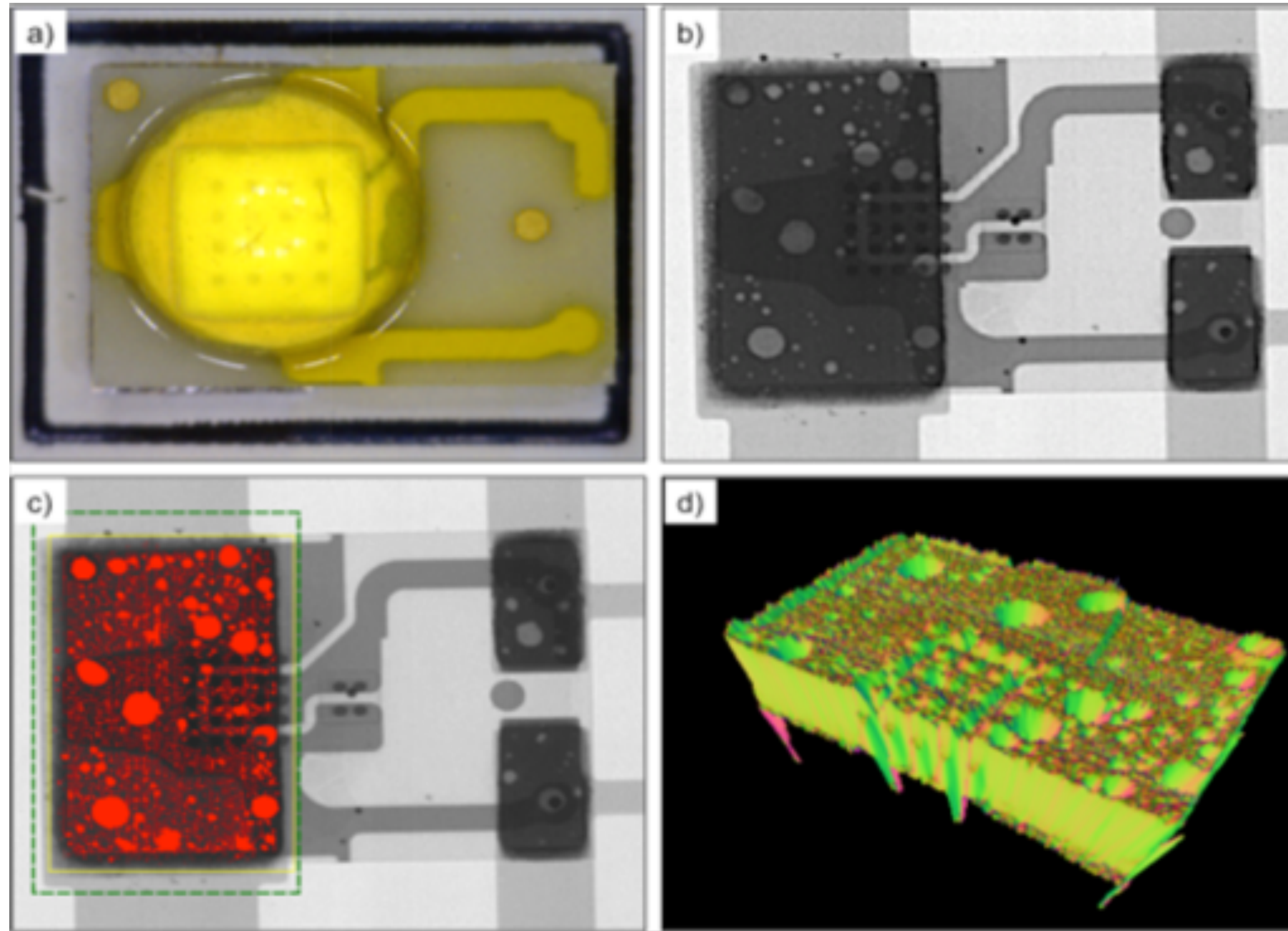
# Void Measurement



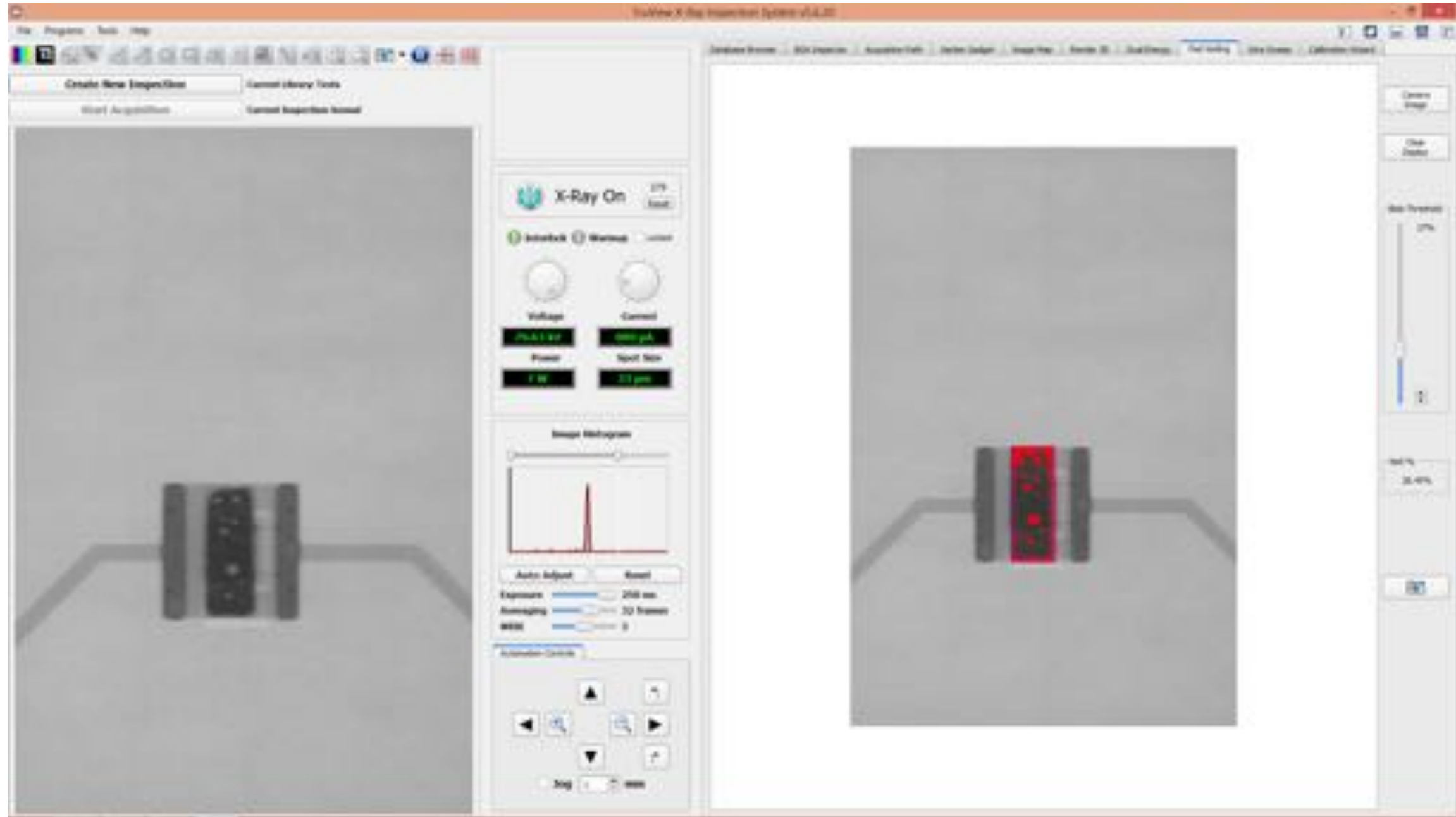
# Solder voids in LED assembly



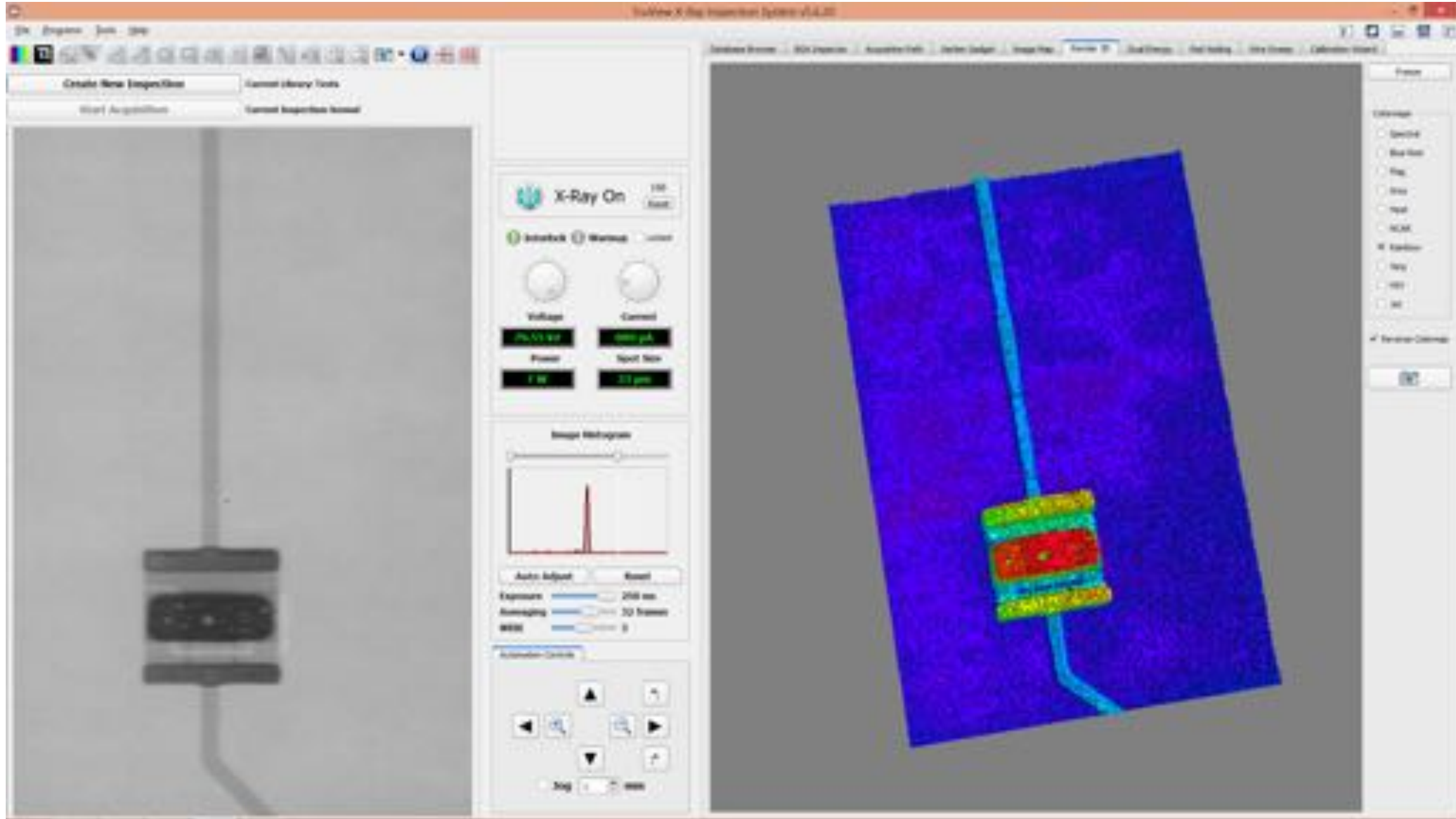


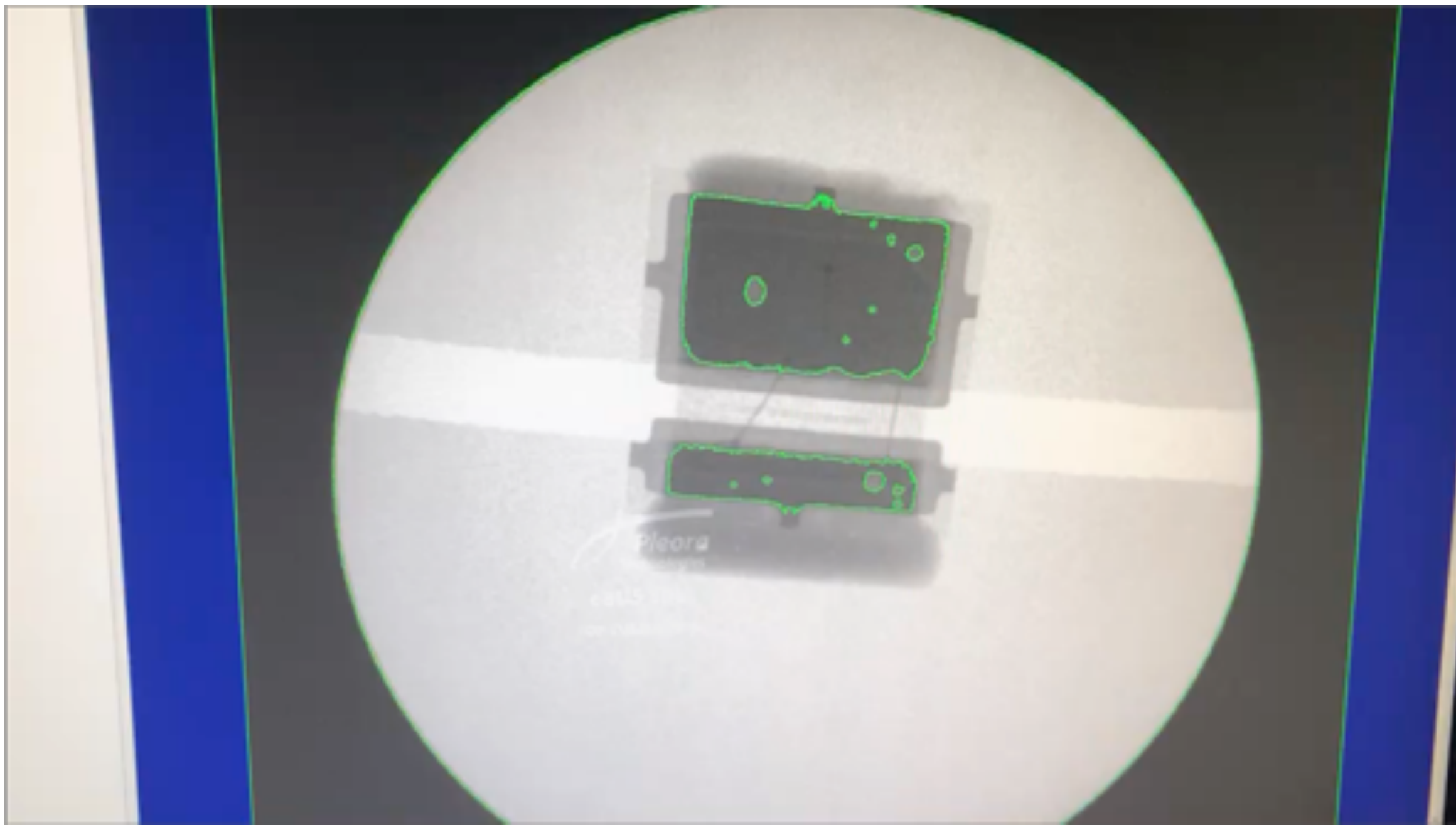


**Figure 2 – a) Photo of LED assembled onto substrate, b) x-ray inspection image of LED, c) x-ray inspection image with identified and measured voids using TruView software, d) 3D rendering of die attach voids**

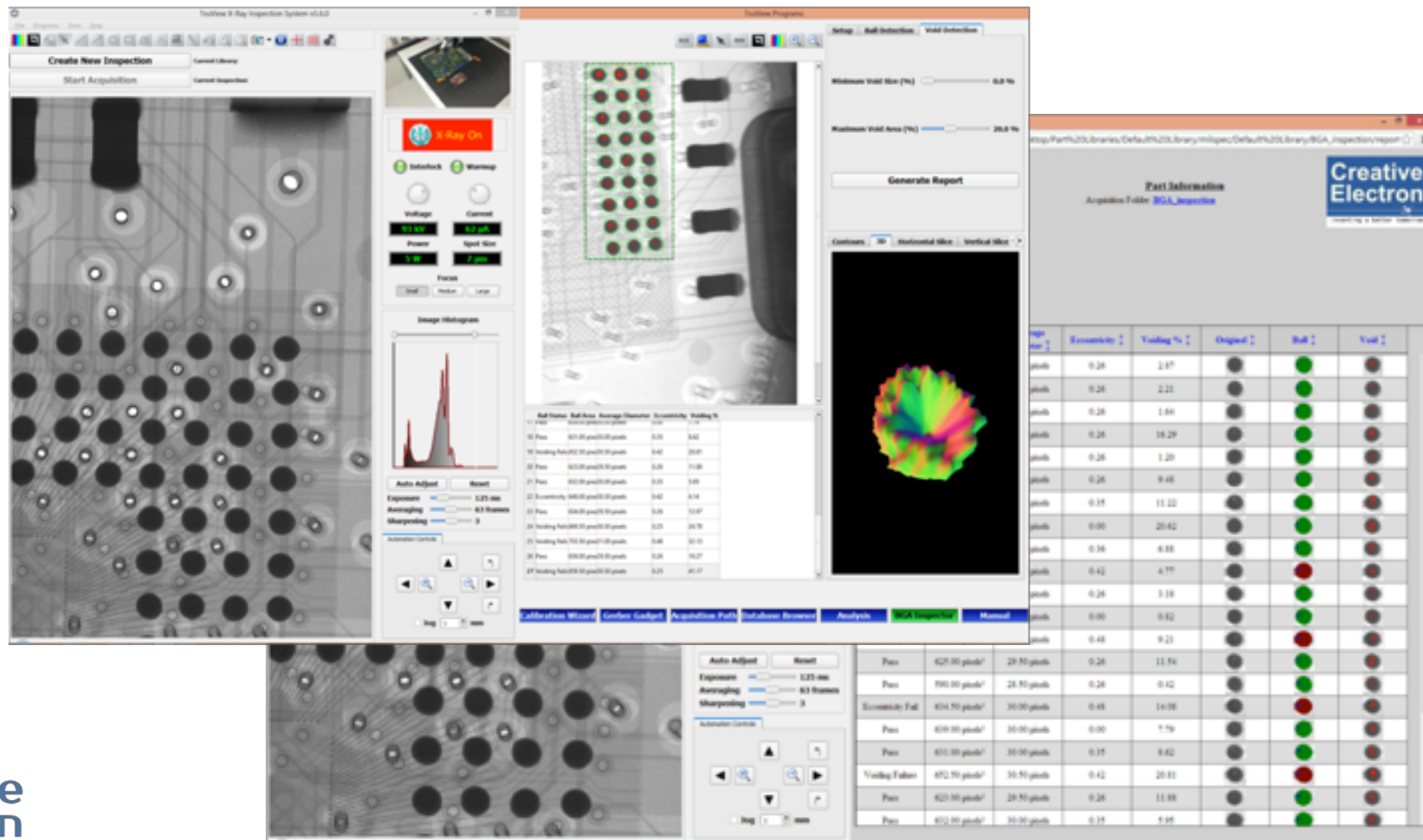








# BGA Inspector



The screenshot displays the BGA Inspector software interface, which includes several key components:

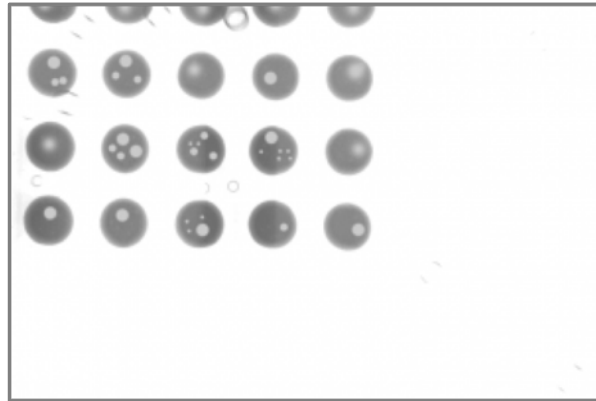
- Control Panel:** Features buttons for 'Create New Inspection', 'Start Acquisition', 'X-Ray On', 'Feedback', and 'Warning'. It also displays real-time 'Voltage' (11.5V) and 'Current' (5.0 mA) readings, along with 'Power' (1.3W) and 'Speed Size' (7.0um).
- Image Histogram:** A graph showing the distribution of pixel intensities in the current image.
- Ball Detection:** A central window showing a live X-ray image of a BGA with a grid of red and green dots indicating detected balls.
- 3D Topography Map:** A colorful 3D map showing the surface profile of the BGA.
- Ball Data Table:** A table listing individual ball measurements. Below is a sample of the data:

Ball No.	Ball Area	Average Diameter	Scarcity	Yield %
19 Pass	621.00 µm²	25.00 µm	0.25	2.87
20 Failing Ball	623.00 µm²	25.00 µm	0.42	20.81
21 Pass	623.00 µm²	25.00 µm	0.25	11.88
22 Pass	623.00 µm²	25.00 µm	0.25	11.88
23 Pass	623.00 µm²	25.00 µm	0.25	11.88
24 Failing Ball	623.00 µm²	25.00 µm	0.25	11.88
25 Failing Ball	750.00 µm²	30.00 µm	0.48	20.81
26 Pass	623.00 µm²	25.00 µm	0.25	11.88
27 Failing Ball	623.00 µm²	25.00 µm	0.25	11.88

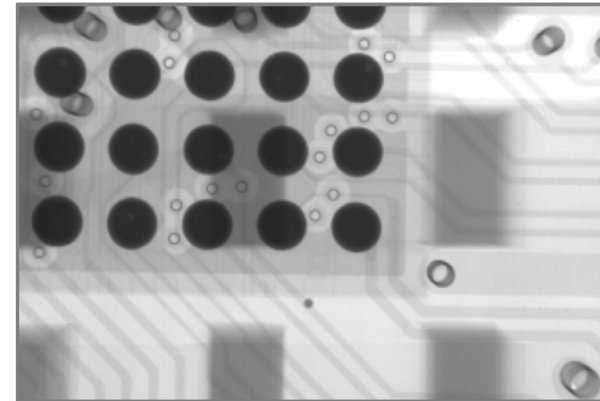
The interface also includes a 'Part Information' window with 'Creative Electron' branding and a 'Generate Report' button. A detailed data table at the bottom right provides a comprehensive overview of the inspection results, including columns for 'Original', 'Ball', and 'Yield' status for each ball.

# Dual Energy

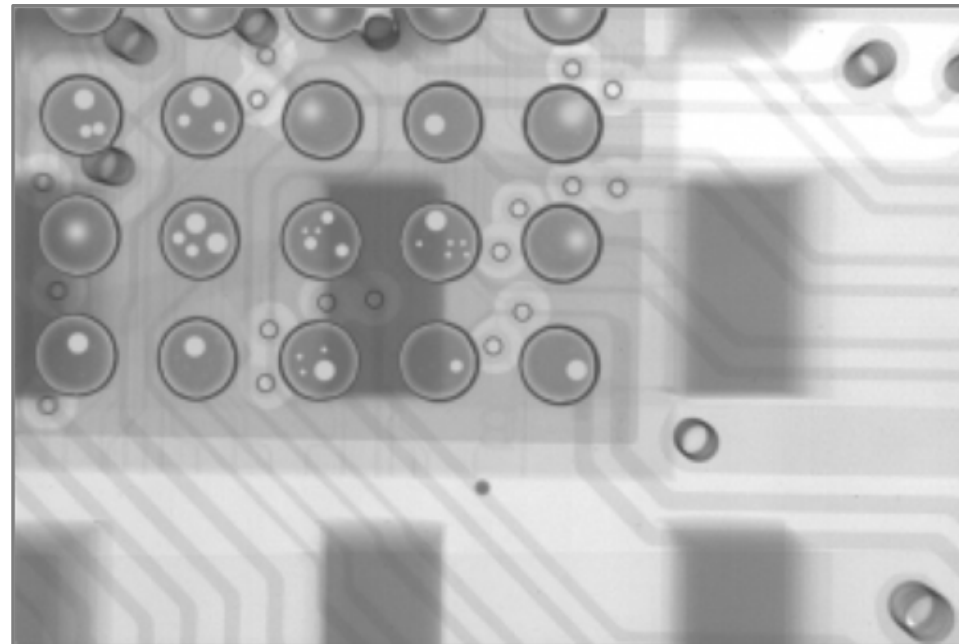
## High Energy Image



## Low Energy Image



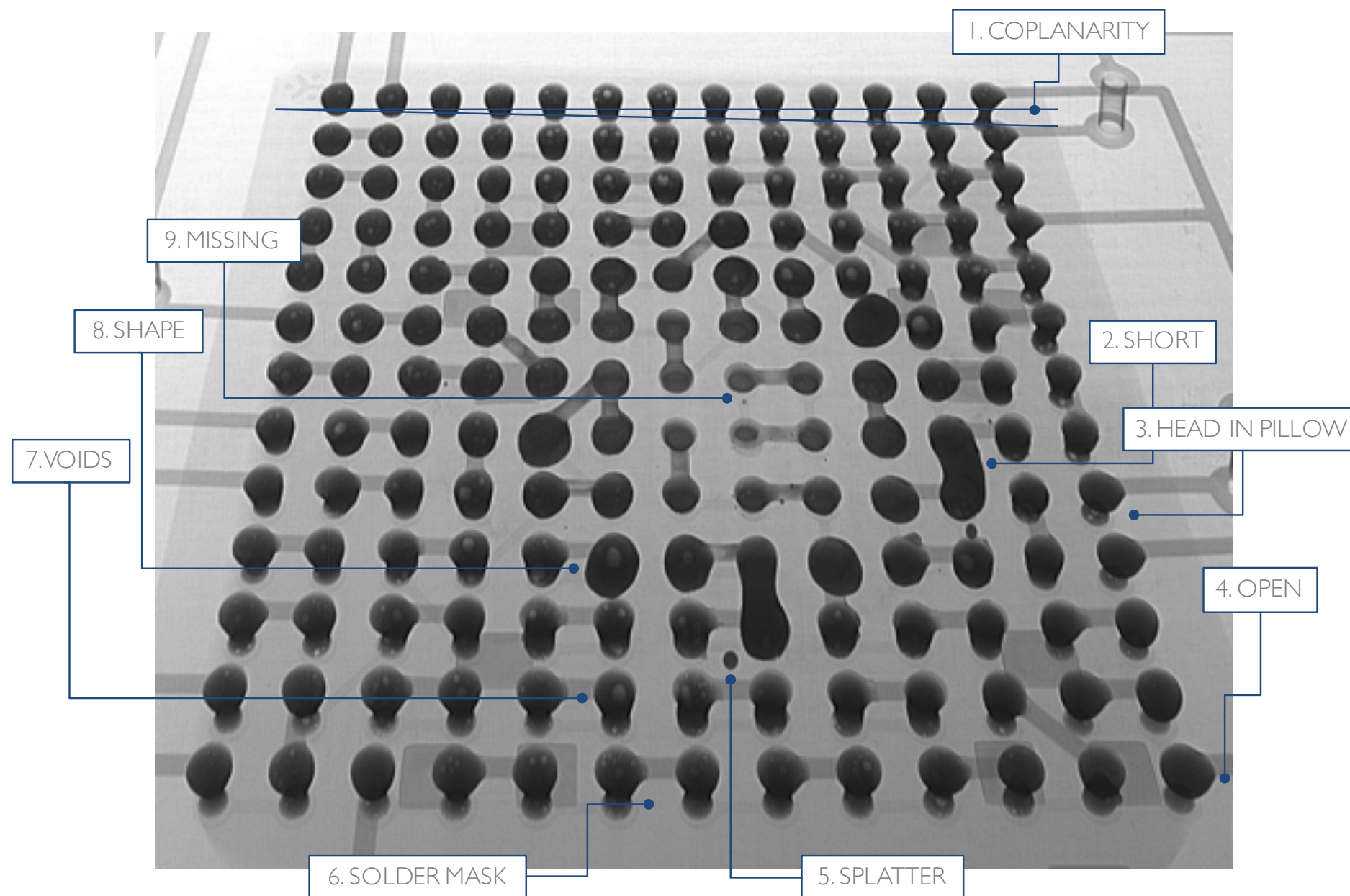
## Dual Energy Image



PATENT PENDING



# The best – and worse – BGA assembly

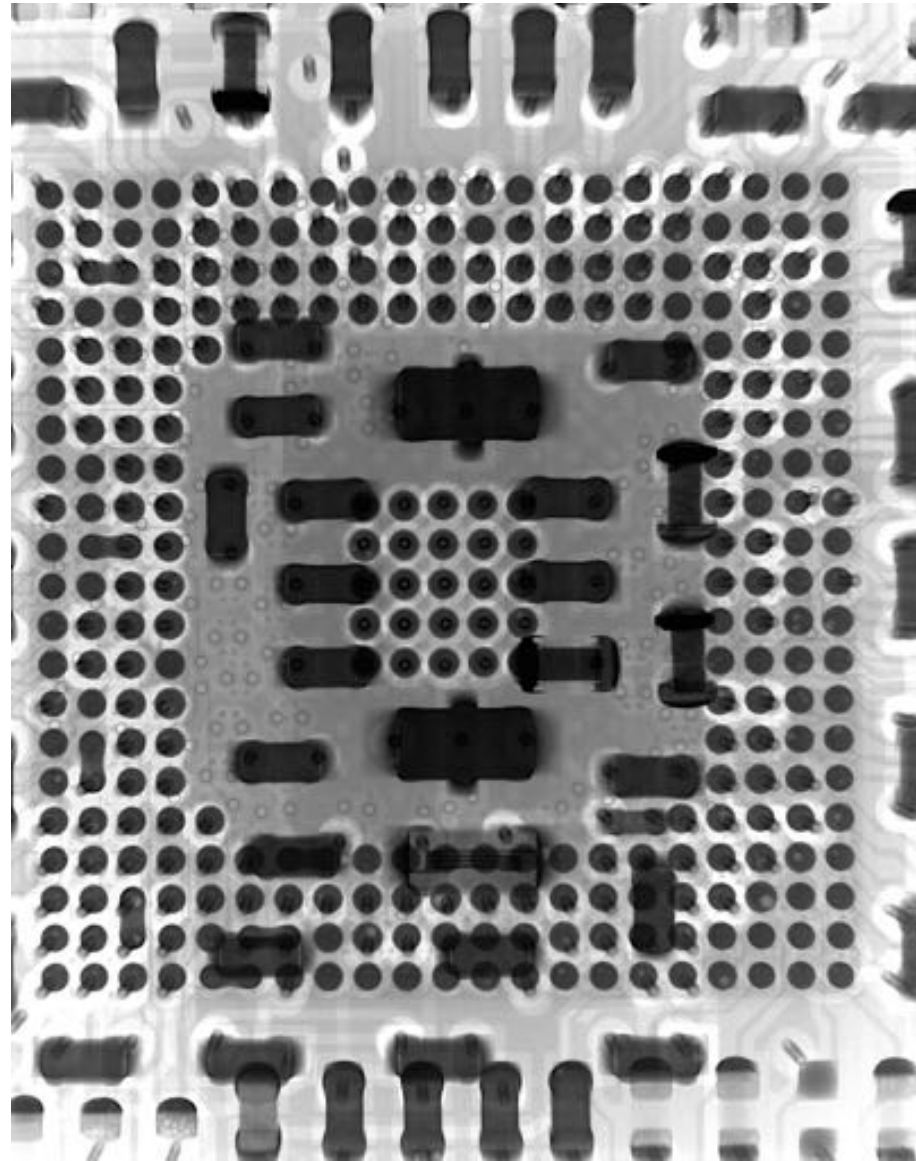


# Design For Inspection: Think 3D!

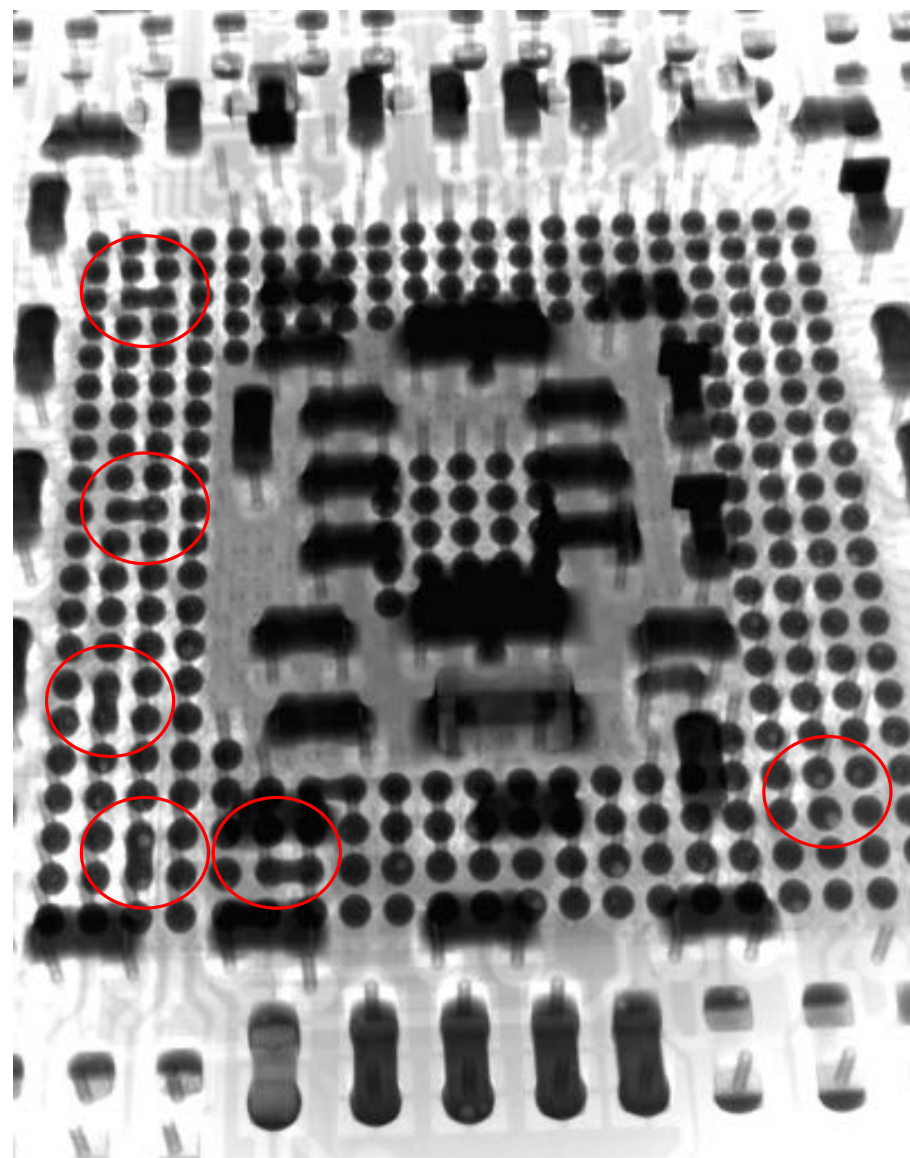
- Components on both sides of board align in such a way it's difficult to assess defects
  - Overlapping BTC
  - Caps under QFN and BGA
  - Heat sinks
- How to avoid it
  - (\$) Design for Inspection
  - (\$\$) 2.5 or (\$\$\$\$) 3D x-ray inspection



# BGA 2D x-ray



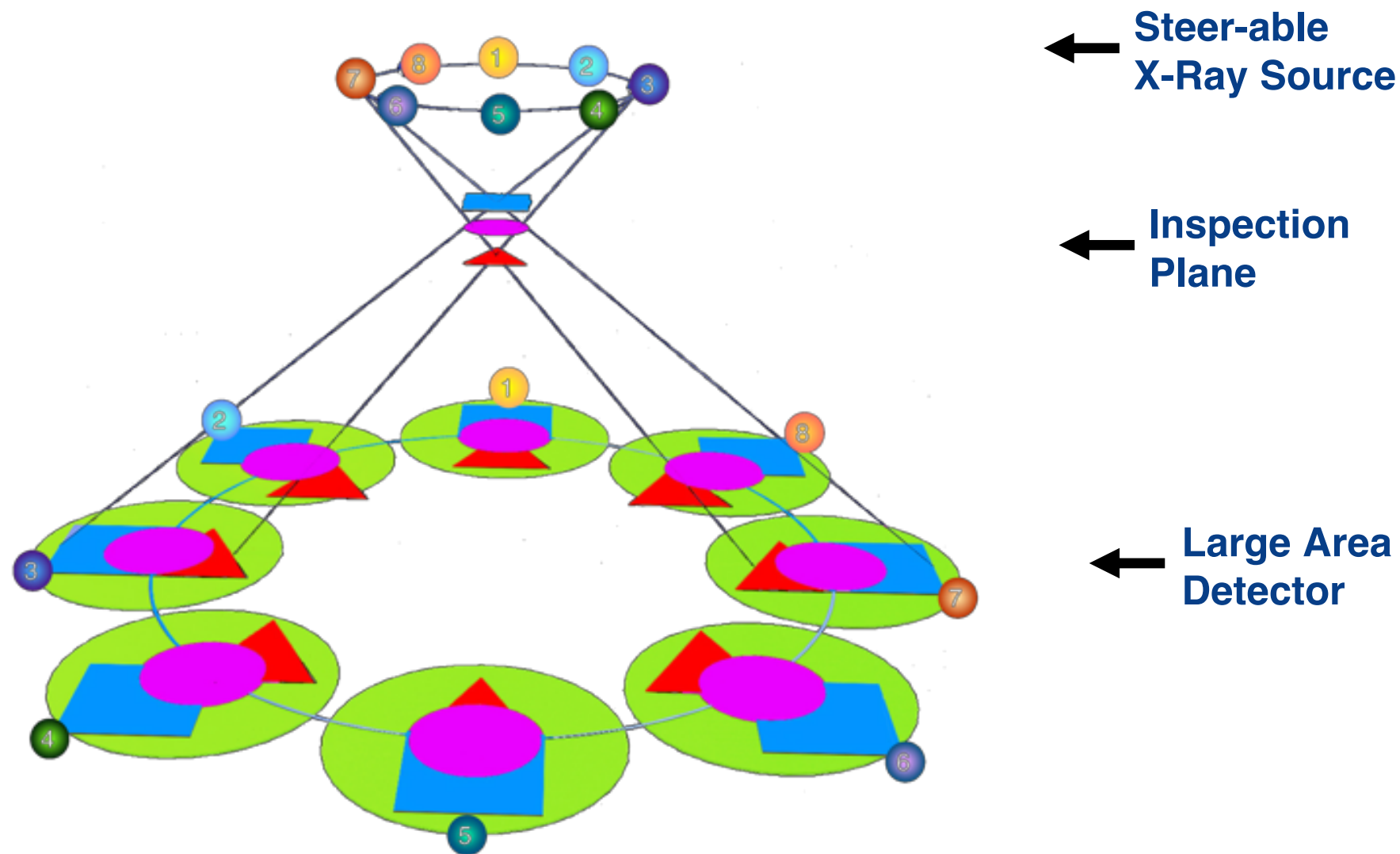
# BGA 2.5D x-ray



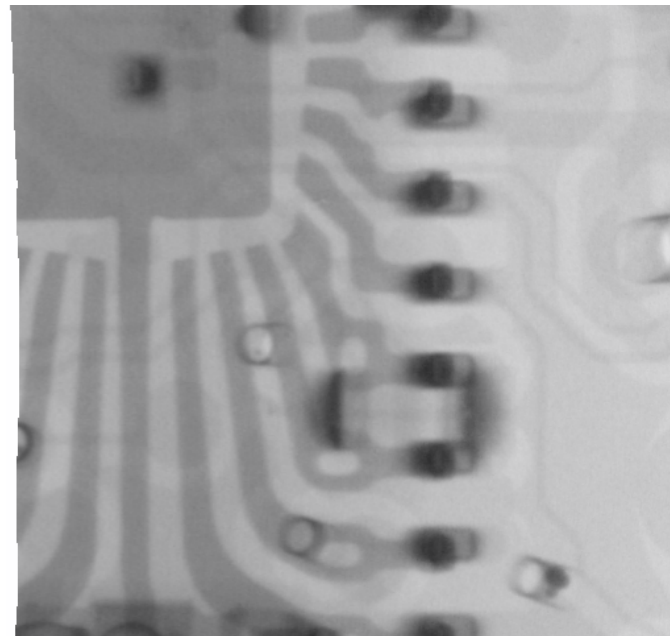


So what's 3D X-Ray Inspection (Computed Tomography)?

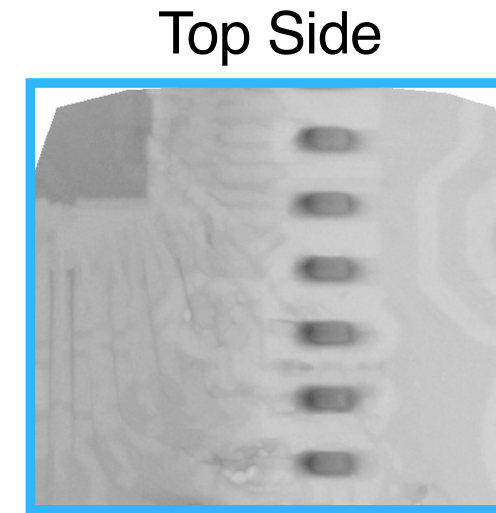
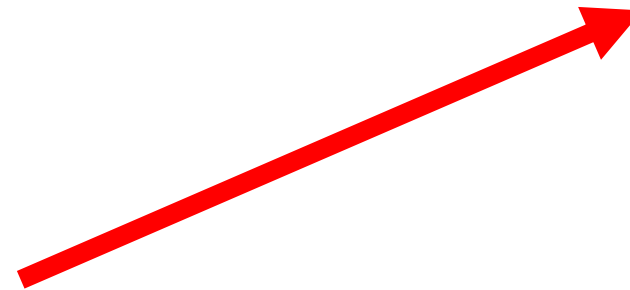
# Principle of Planar CT: 3D x-ray Multiple **Transmission** Images



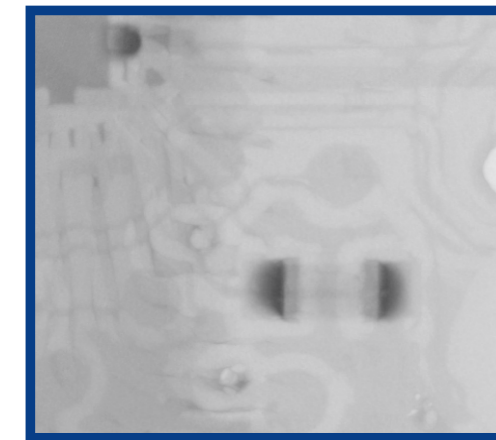
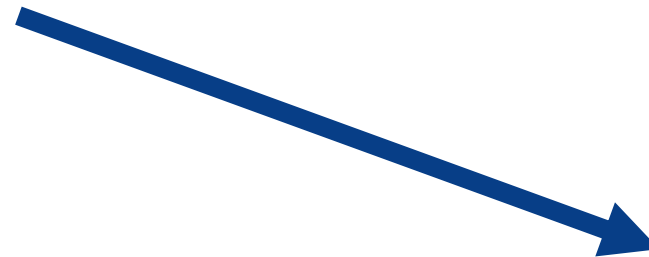
# Principle of Planar CT



Use multiple off-axis x-ray images to separate top/bottom overlapping or obscured solder connections



Cross Section x-ray provides the capability to generate un-obscured views of top and bottom side components

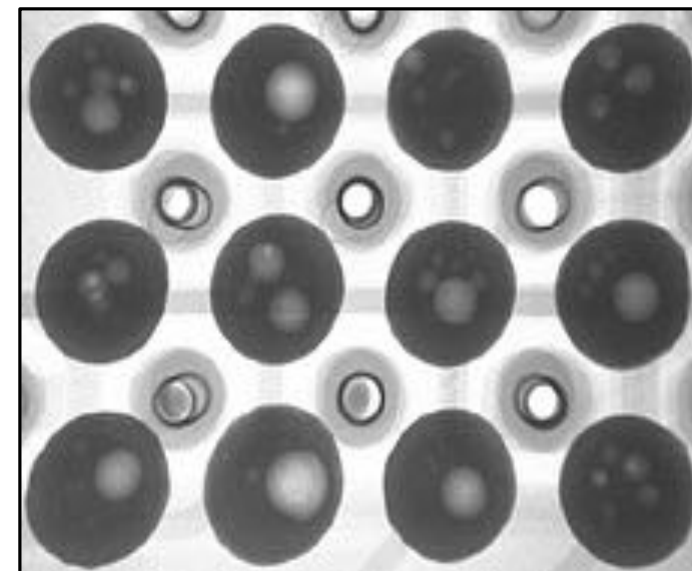


Bottom Side

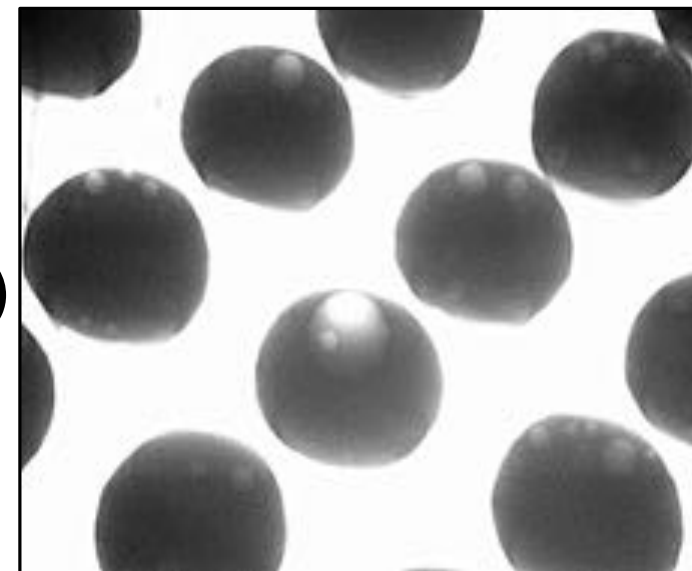




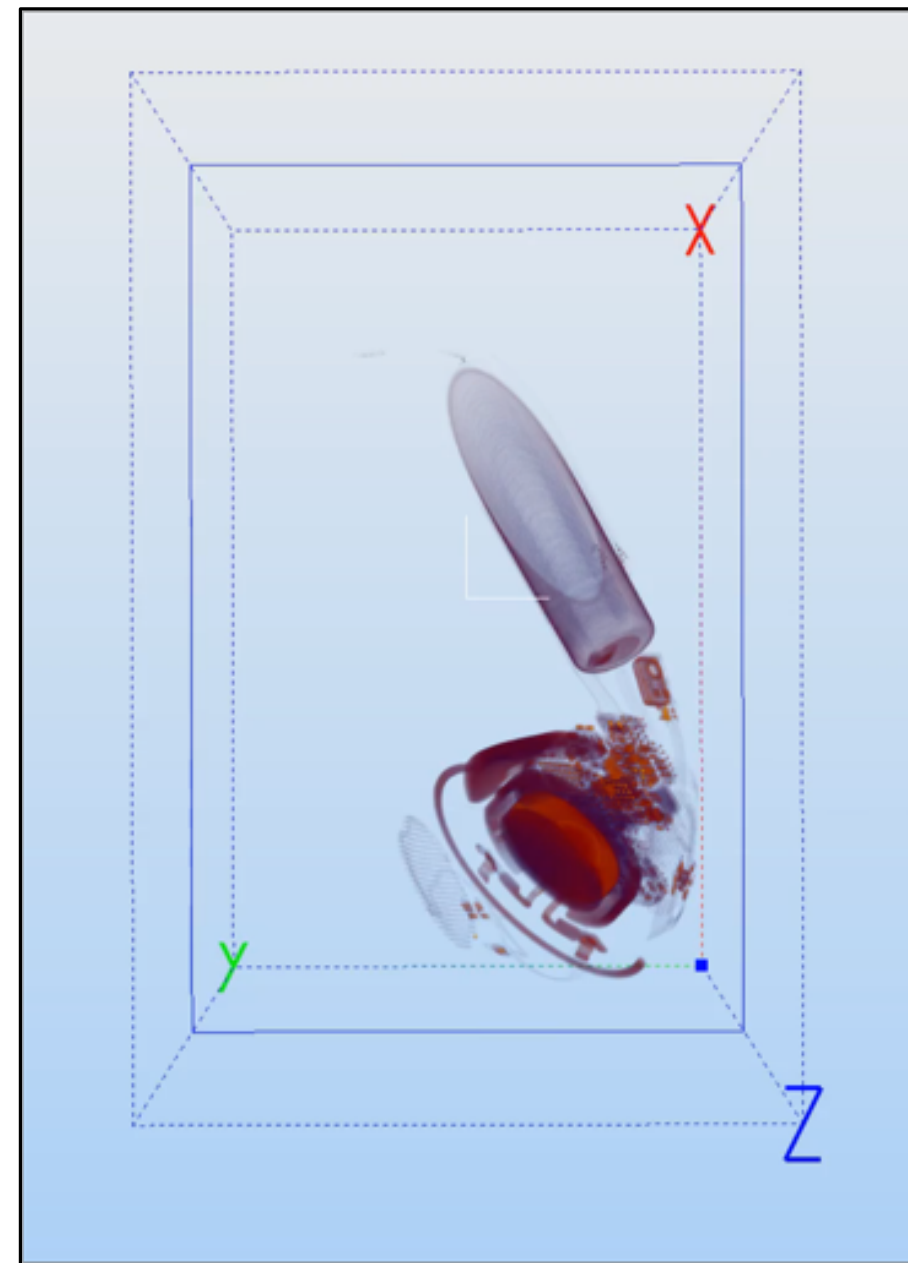
2D



2.5D



3D



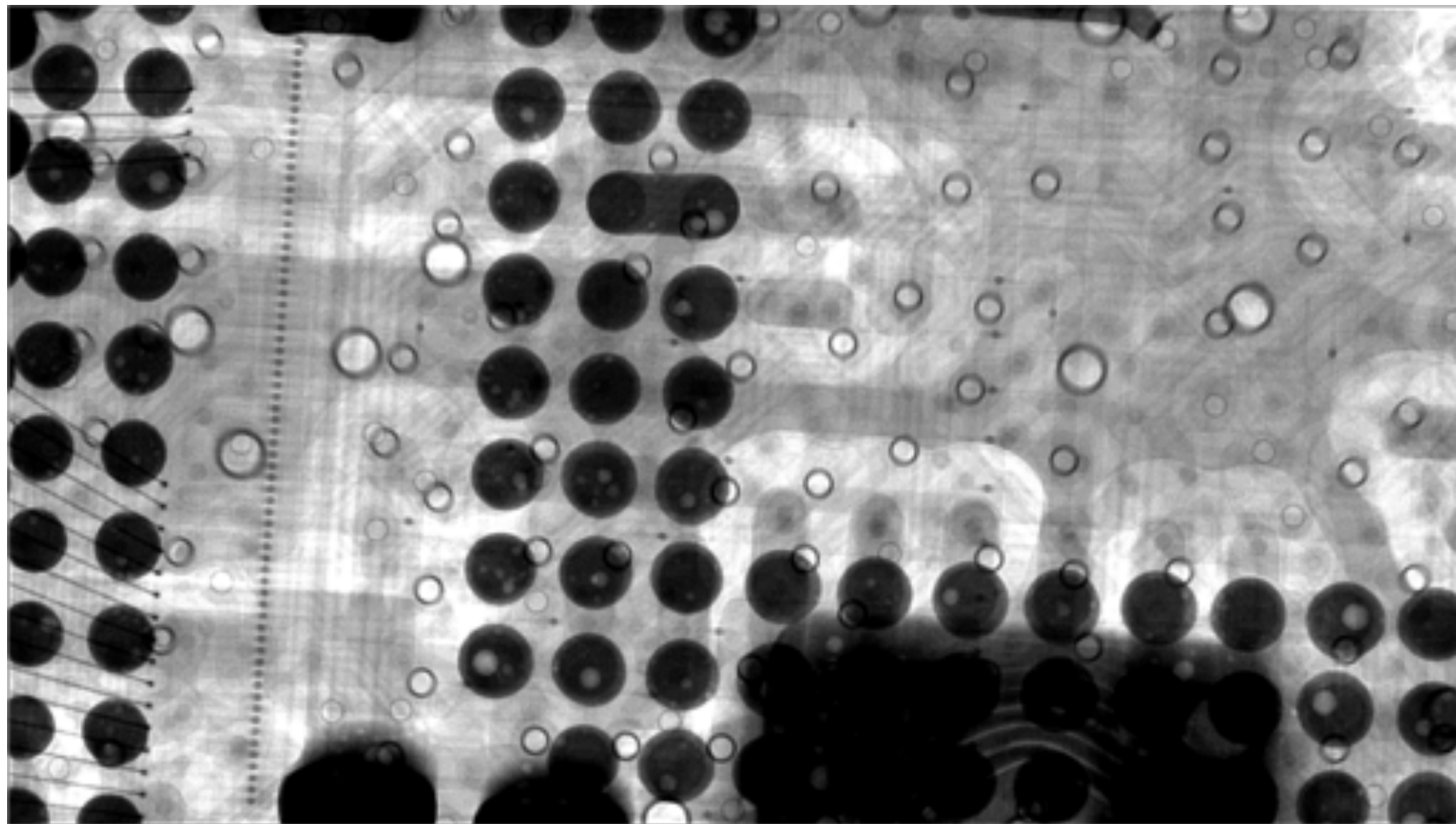


# Design for Inspection

- Think carefully about component placement when designing PCB
- Place parts so 2.5 and 3D x-ray are not needed.
- Goal is to have the whole board inspected with 2D x-ray
  - Faster
  - Better quality
  - Cheaper

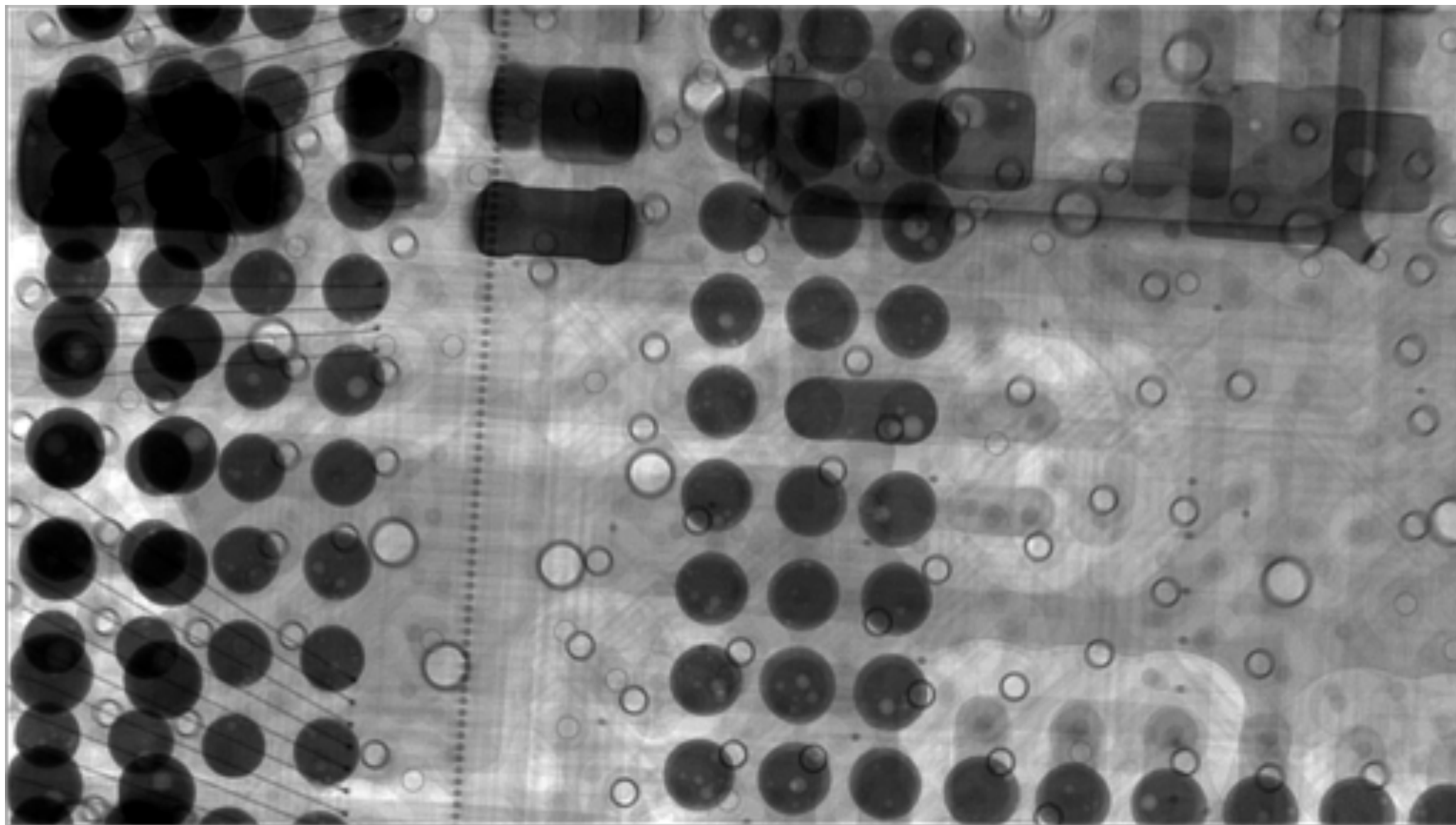


# Power components under BGA





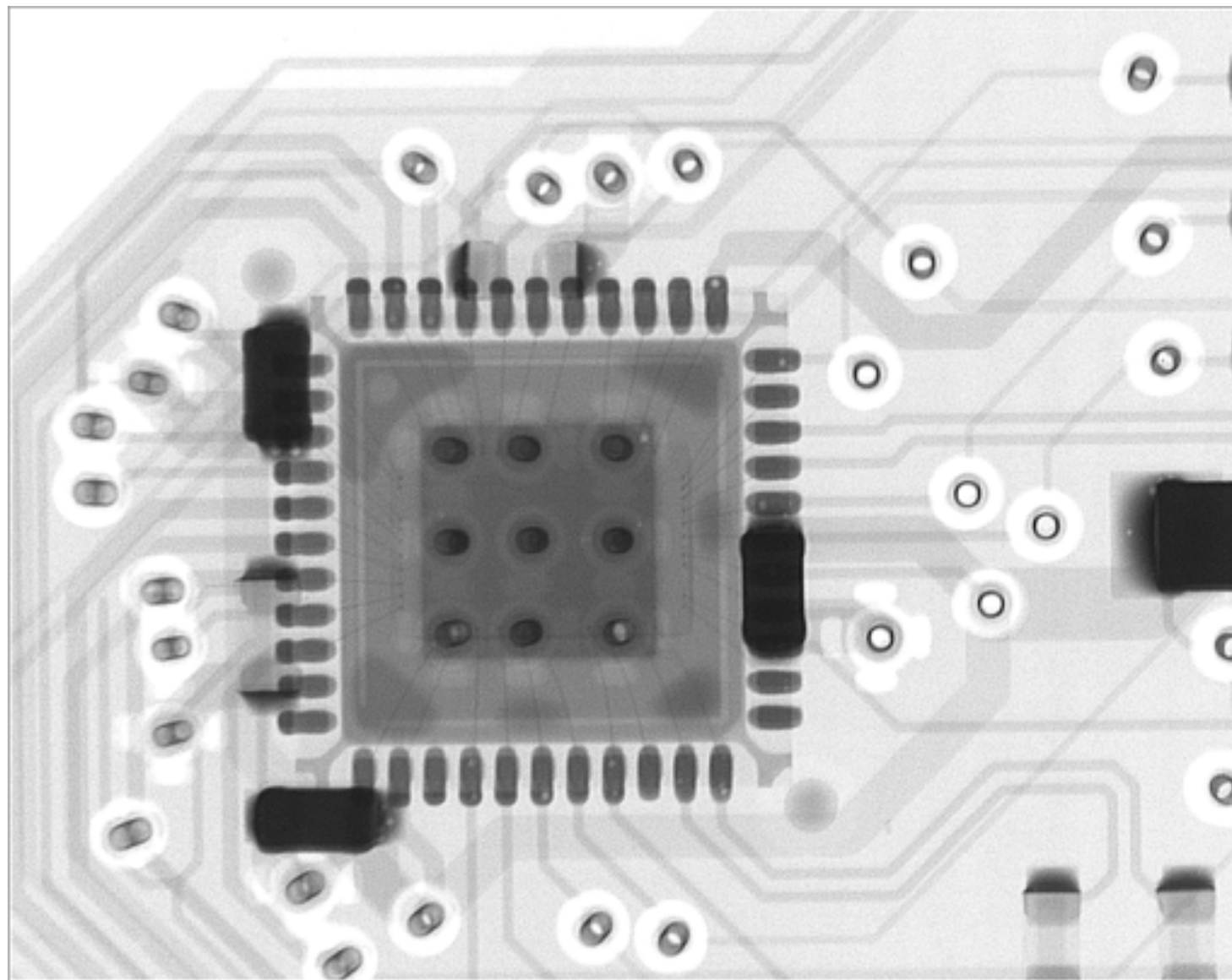
# Caps under BGA

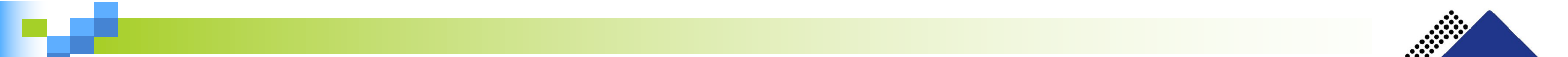




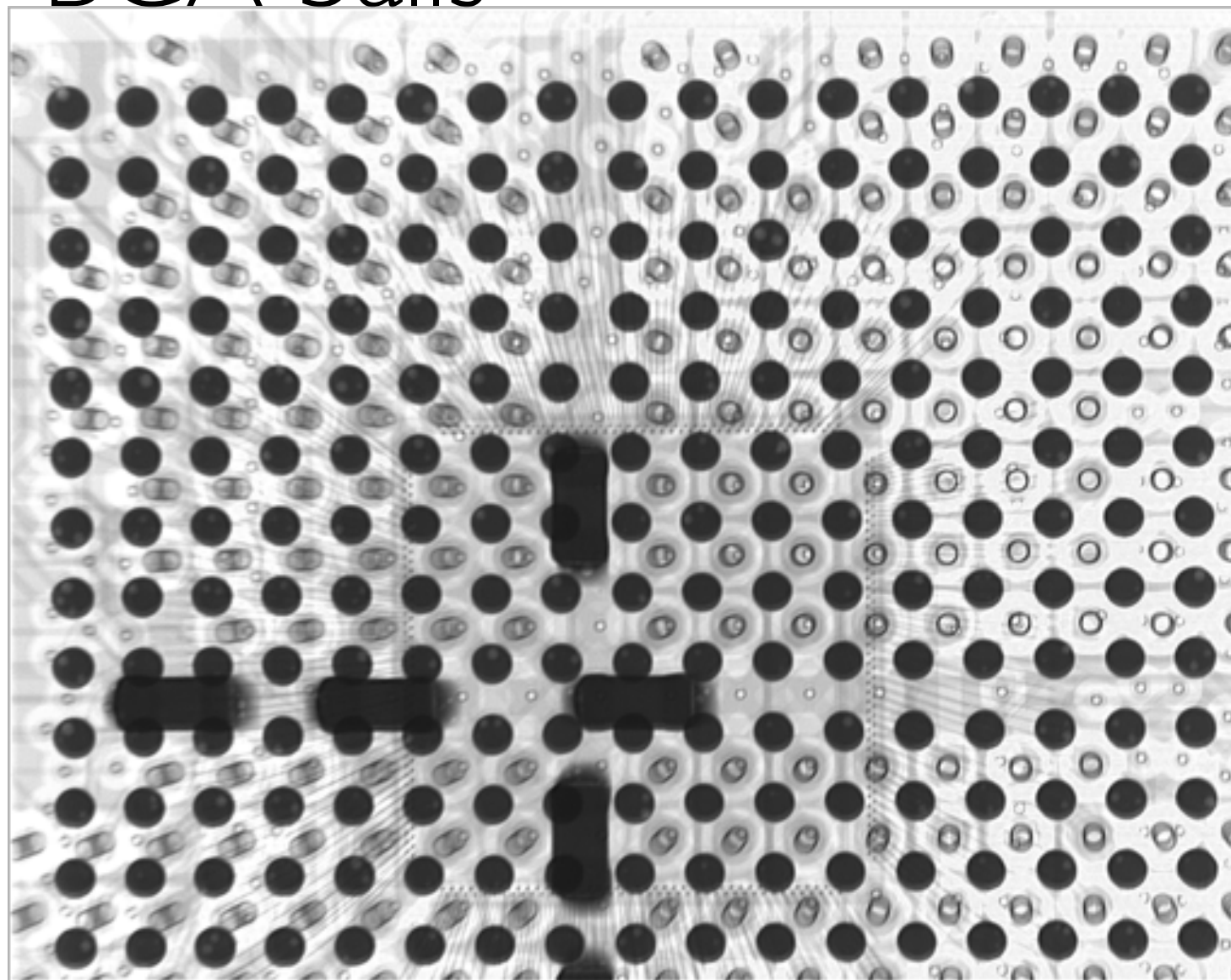


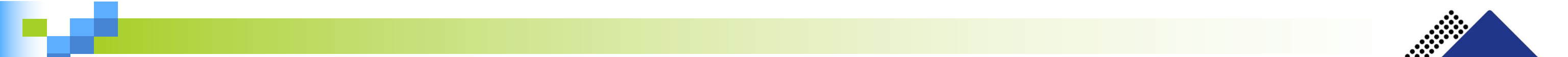
# Caps under QFN leads



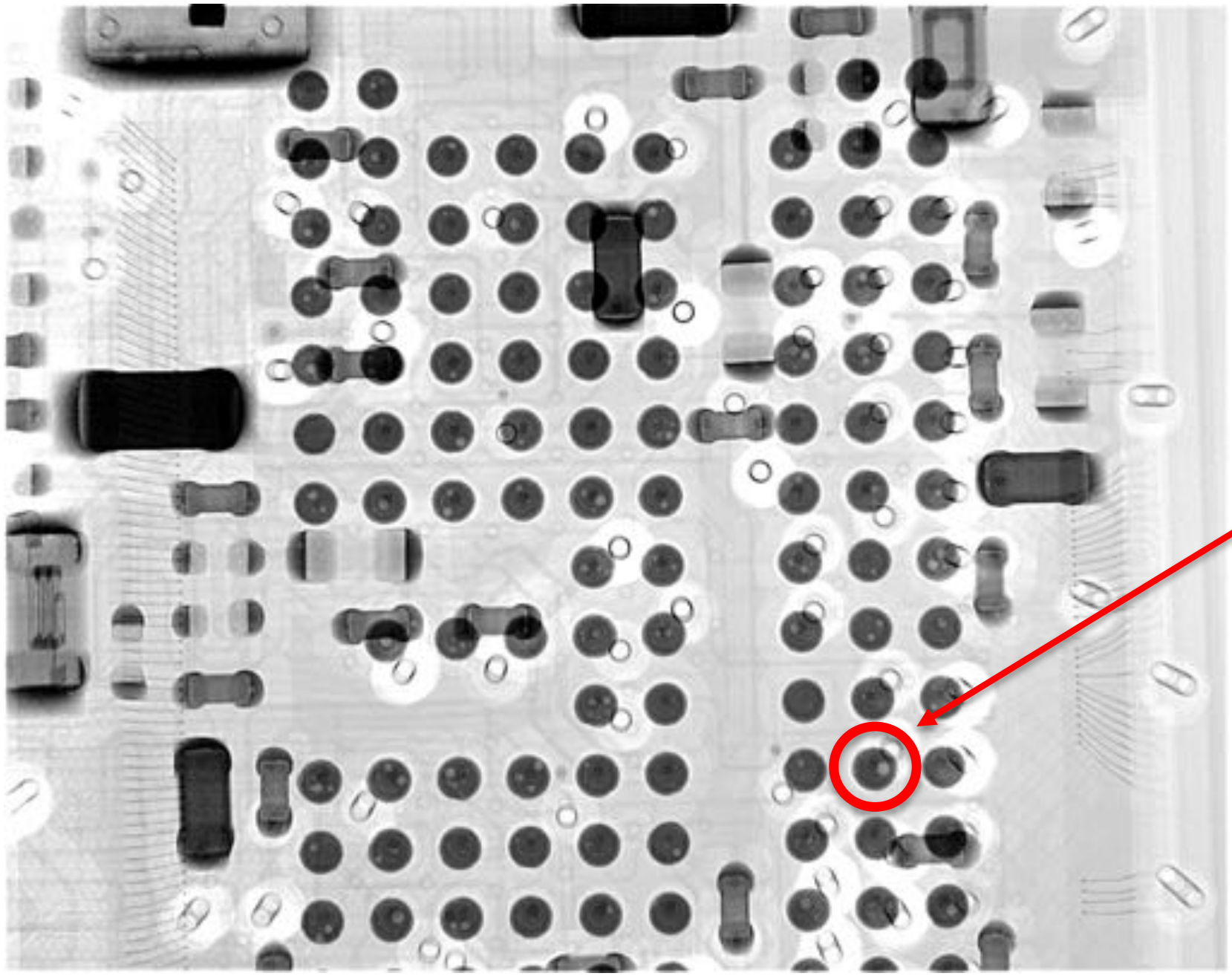


# Caps under BGA balls



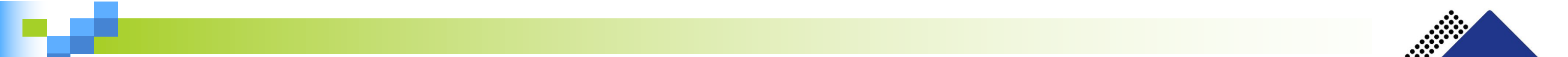


# Sample

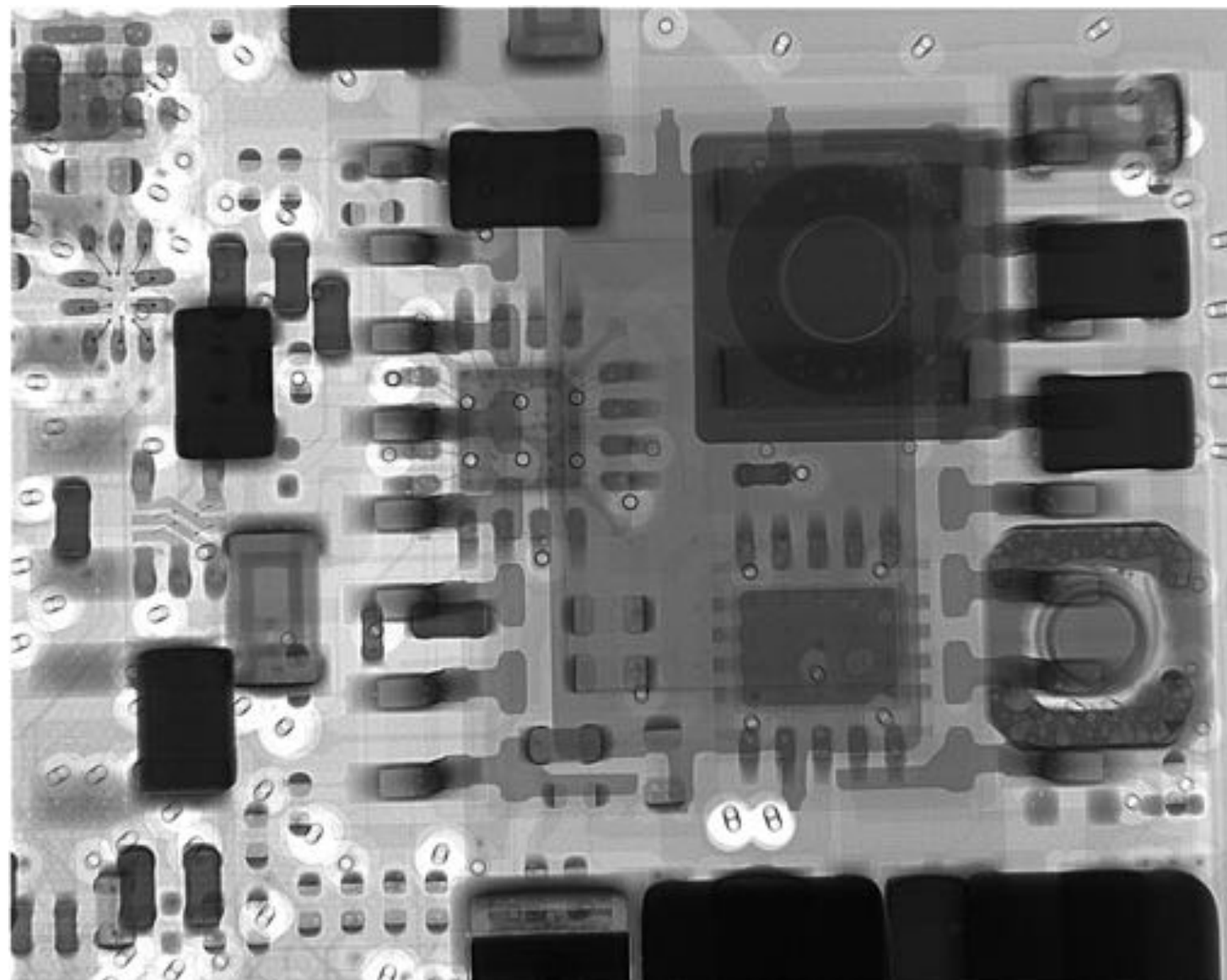


Voiding



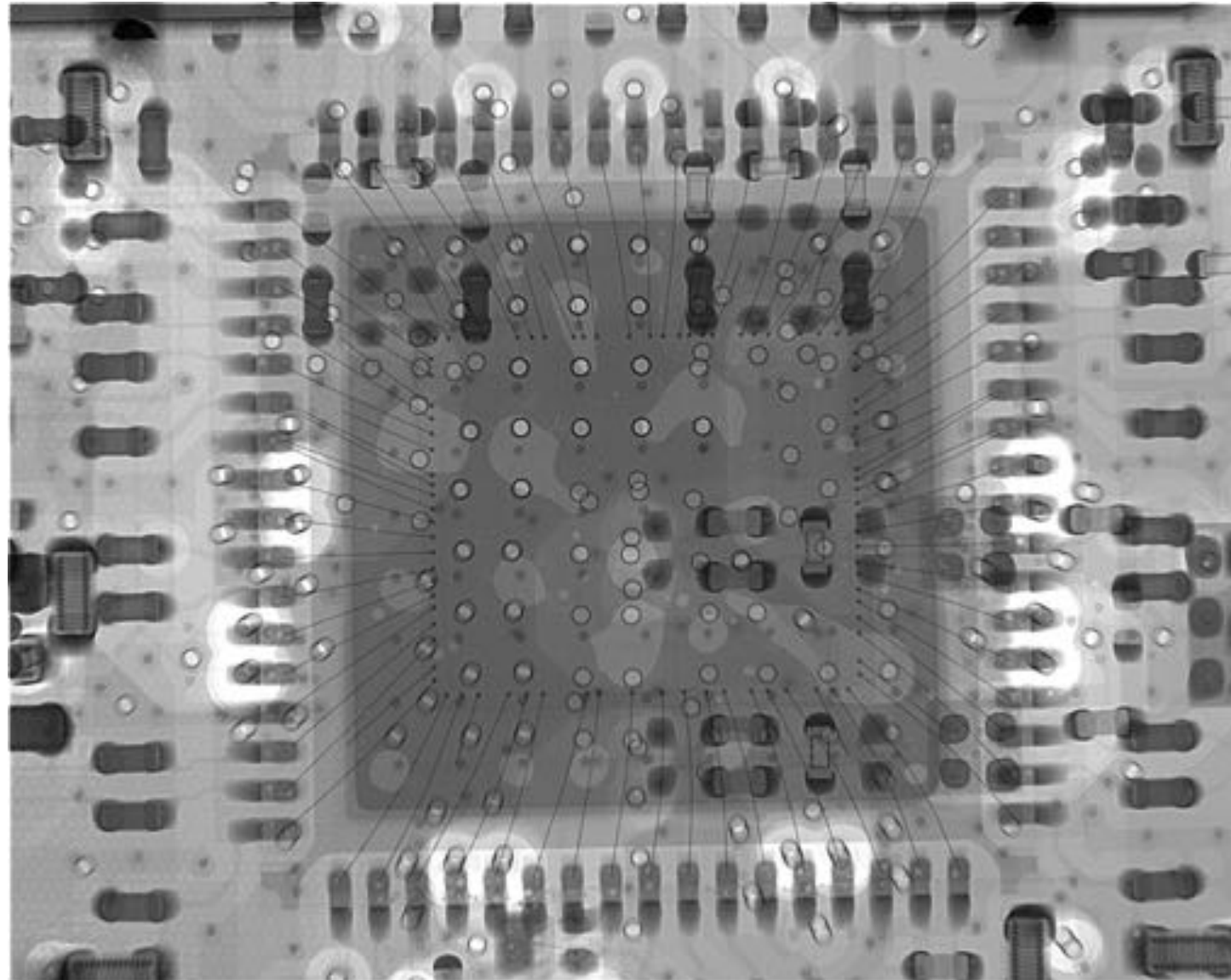


# Complex construction



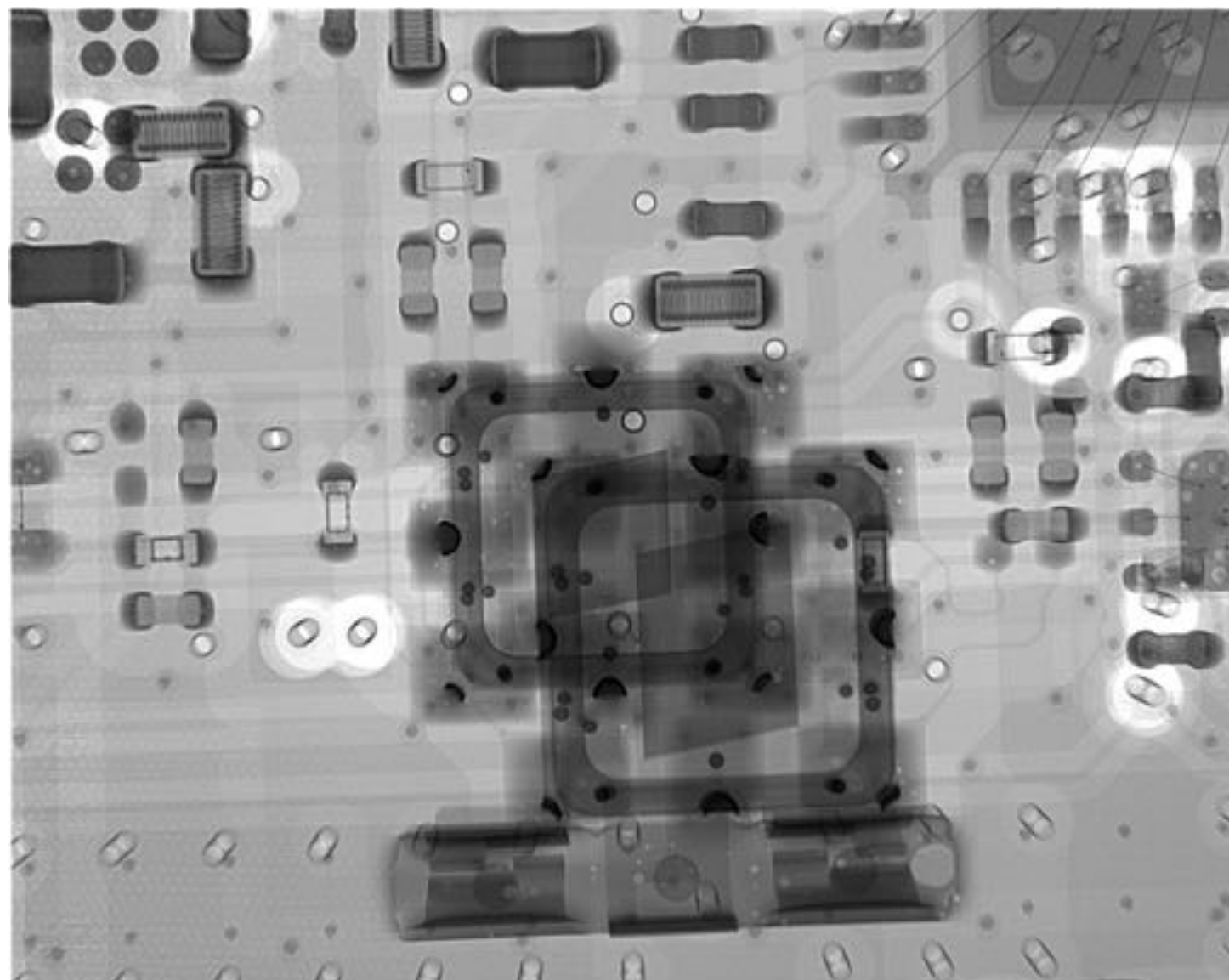


# Caps and QFN





# QFN overlap





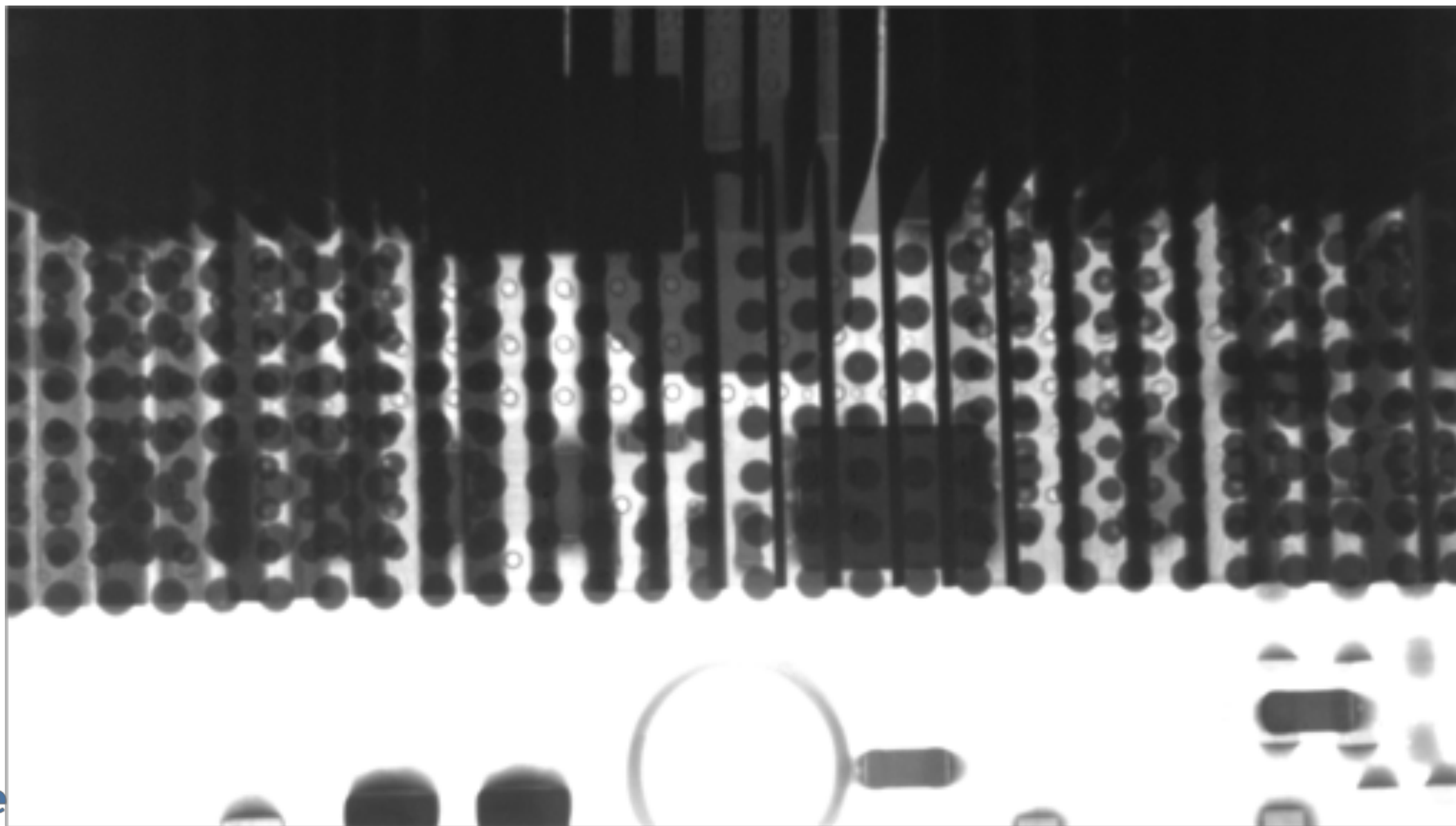
# Heat sink







# Heat sink: x-ray



# Heat sink removed: x-ray





# Think 3D!

- X-rays are a requirement when inspecting BTC
- DFM + DFI: Easier to design for inspection
- Some applications require 2.5D & 3D x-ray
- Miniaturization major driver for high resolution, high magnification, x-ray inspection

# Design for Inspection – DFI

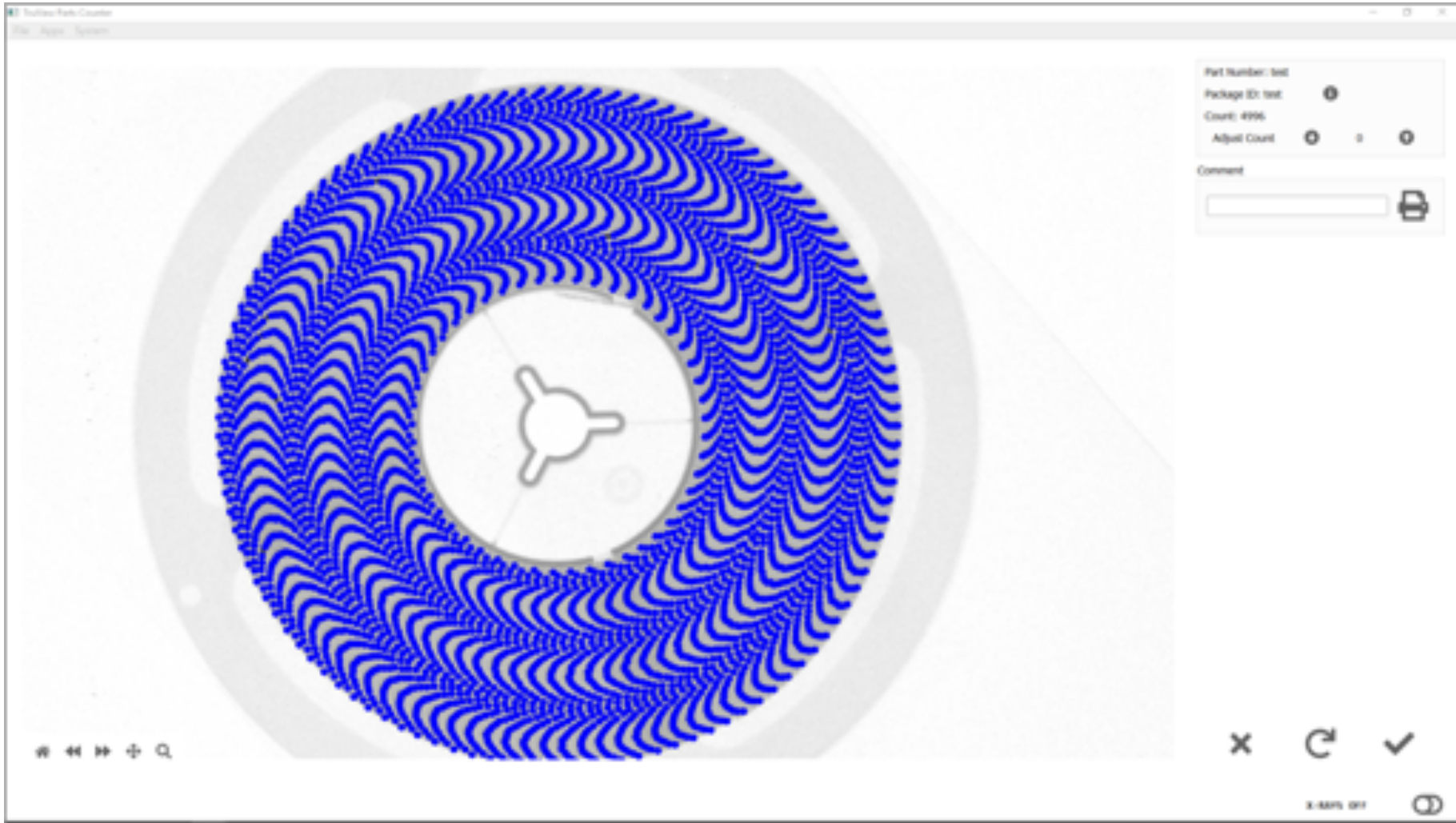
- The right time to think about x-ray inspection is during PCB layout
- After board is assembled is too late to improve x-ray inspection ability



# Material Management & Counterfeit Electronics



# TruView™ Parts Counter AI



# TruView Parts Counter : ERP & MRP

MYCRONIC



{ REST }



ODBC





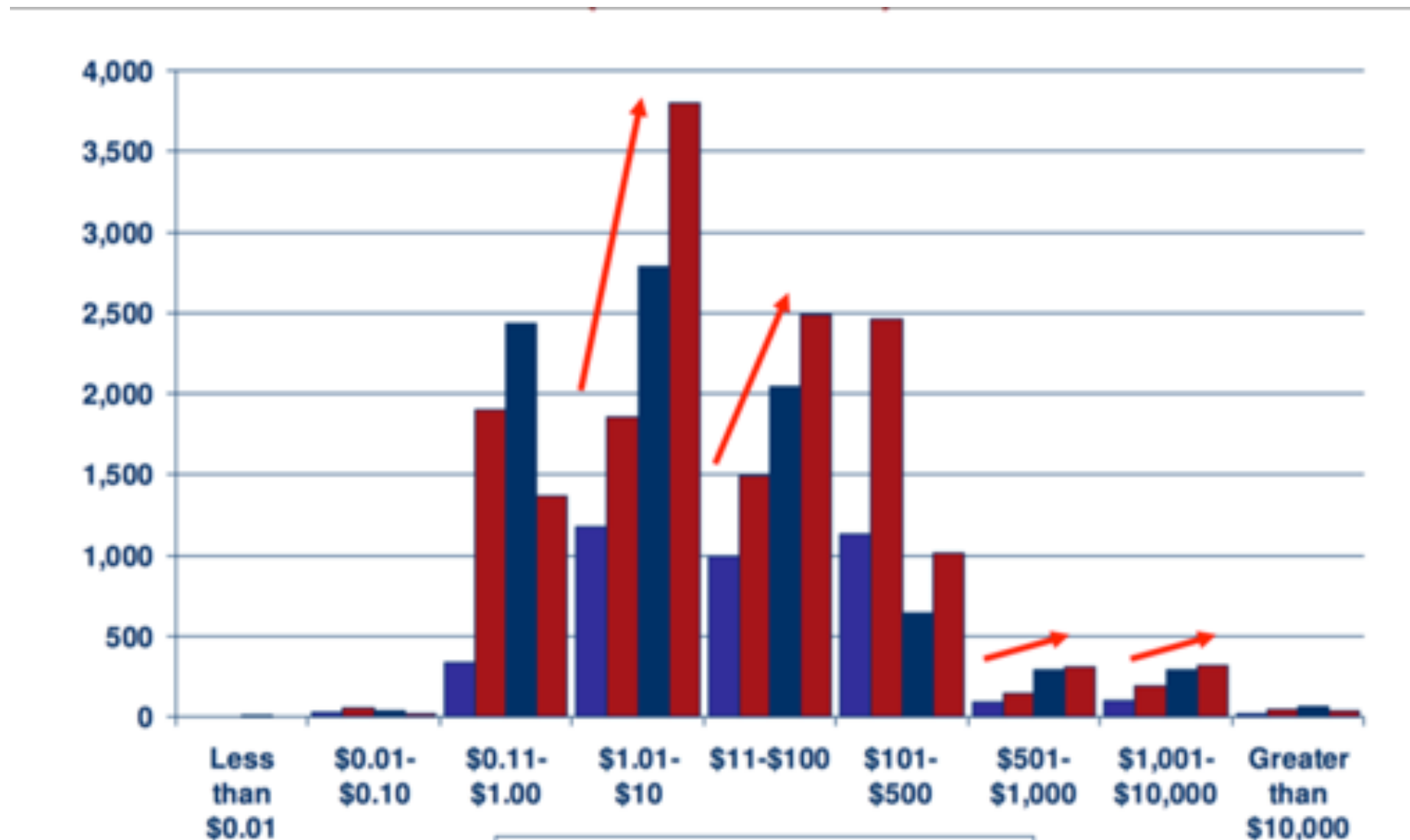
# The counterfeit electronics problem

- ✱ Surplus stock of electronic components dumped into the market further establishing the broker and grey markets
- ✱ Huge amounts of scrap electronics
- ✱ Components made obsolete
- ✱ Need for short delivery time
- ✱ Massive cost reduction pressures on OEM buyers for double digit price reductions
- ✱ Buying and selling via the internet became common practice

# Component Harvesting



# Only expensive parts are counterfeited...





Anything wrong with these caps?

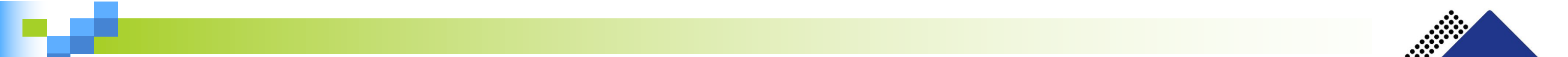




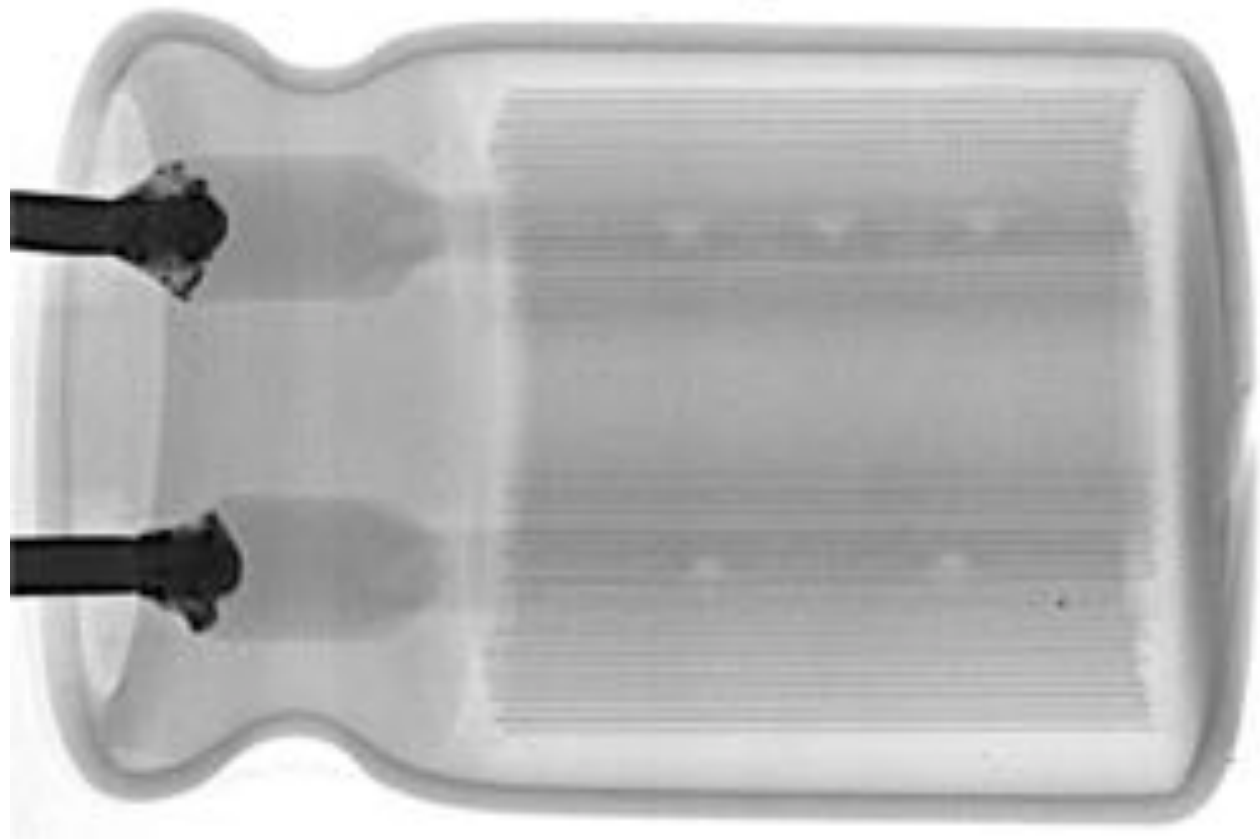
# What happens when you got the wrong cap?



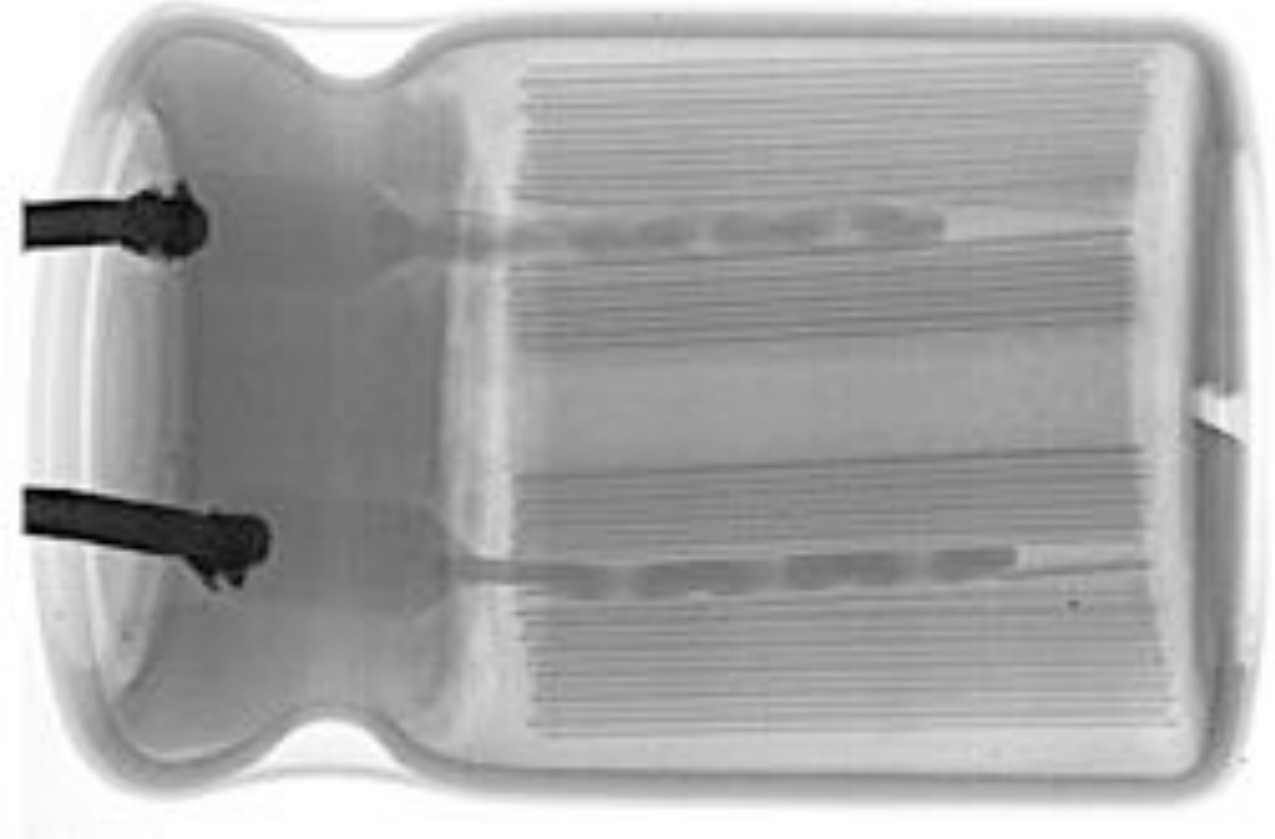


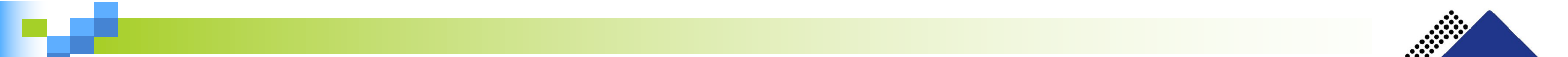


**Reference Component**

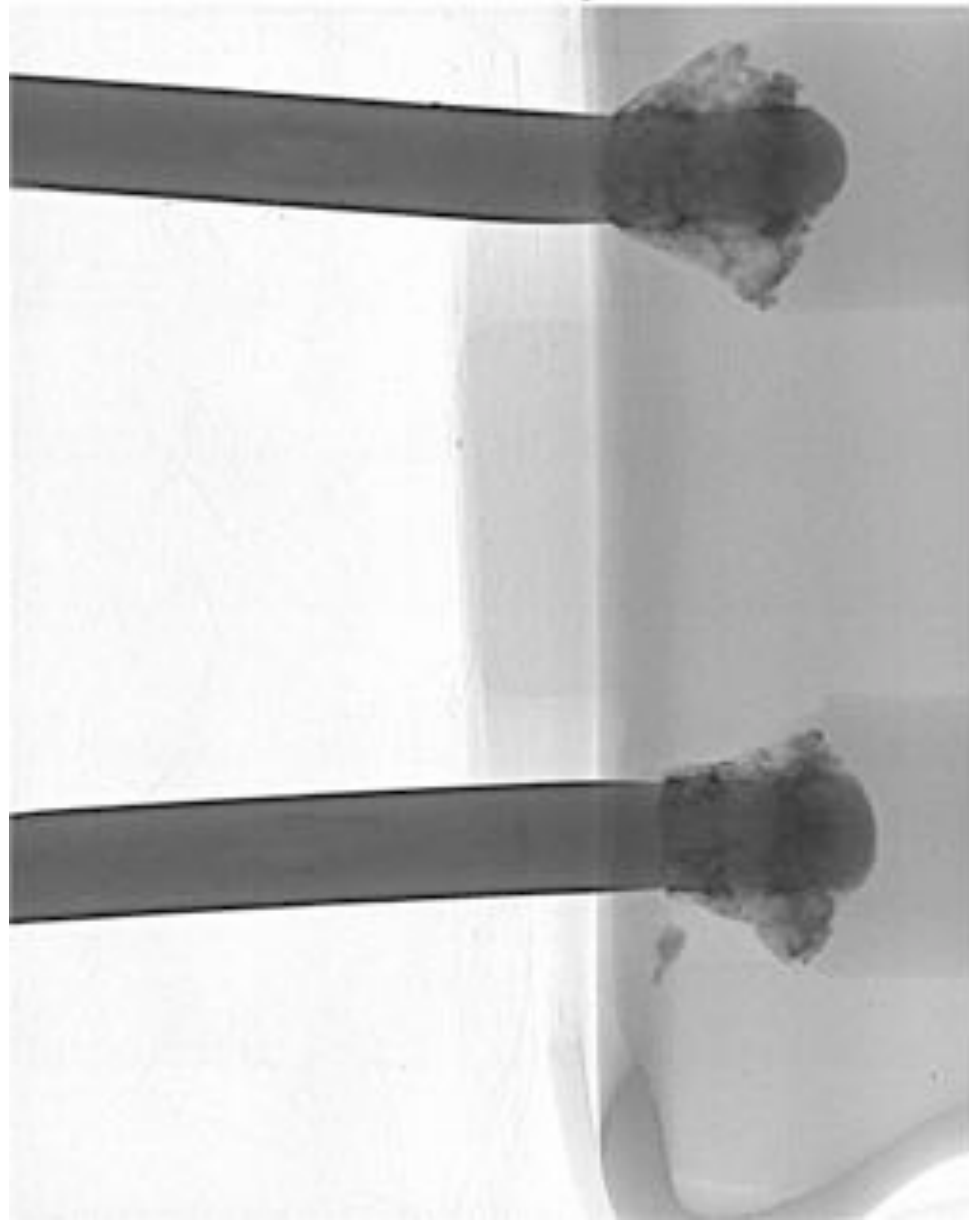


**Suspect Counterfeit Component**

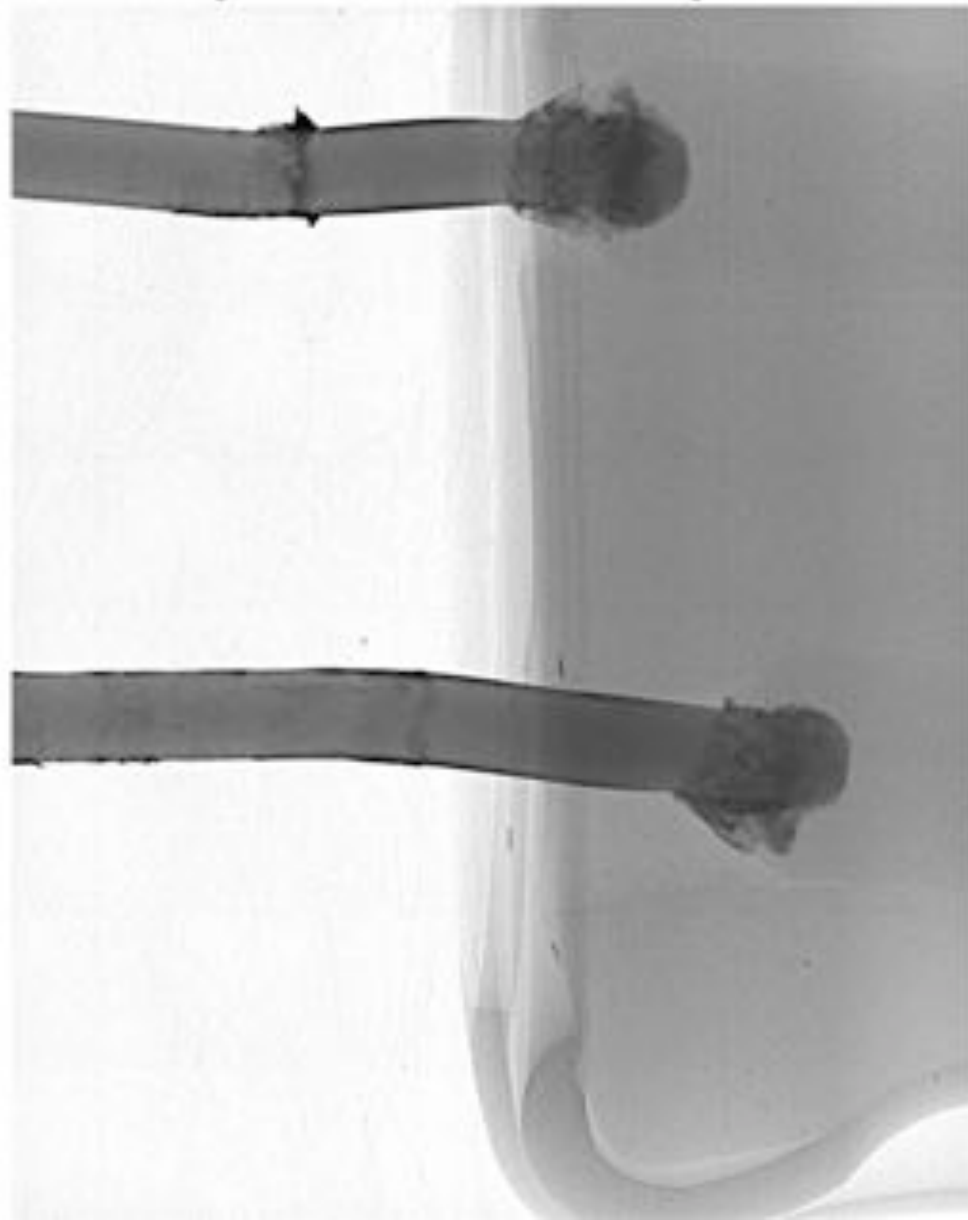




**Reference Component**



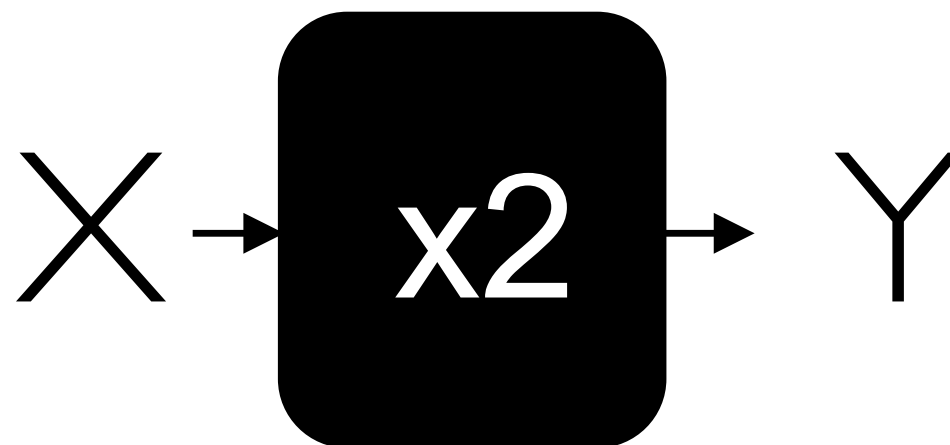
**Suspect Counterfeit Component**



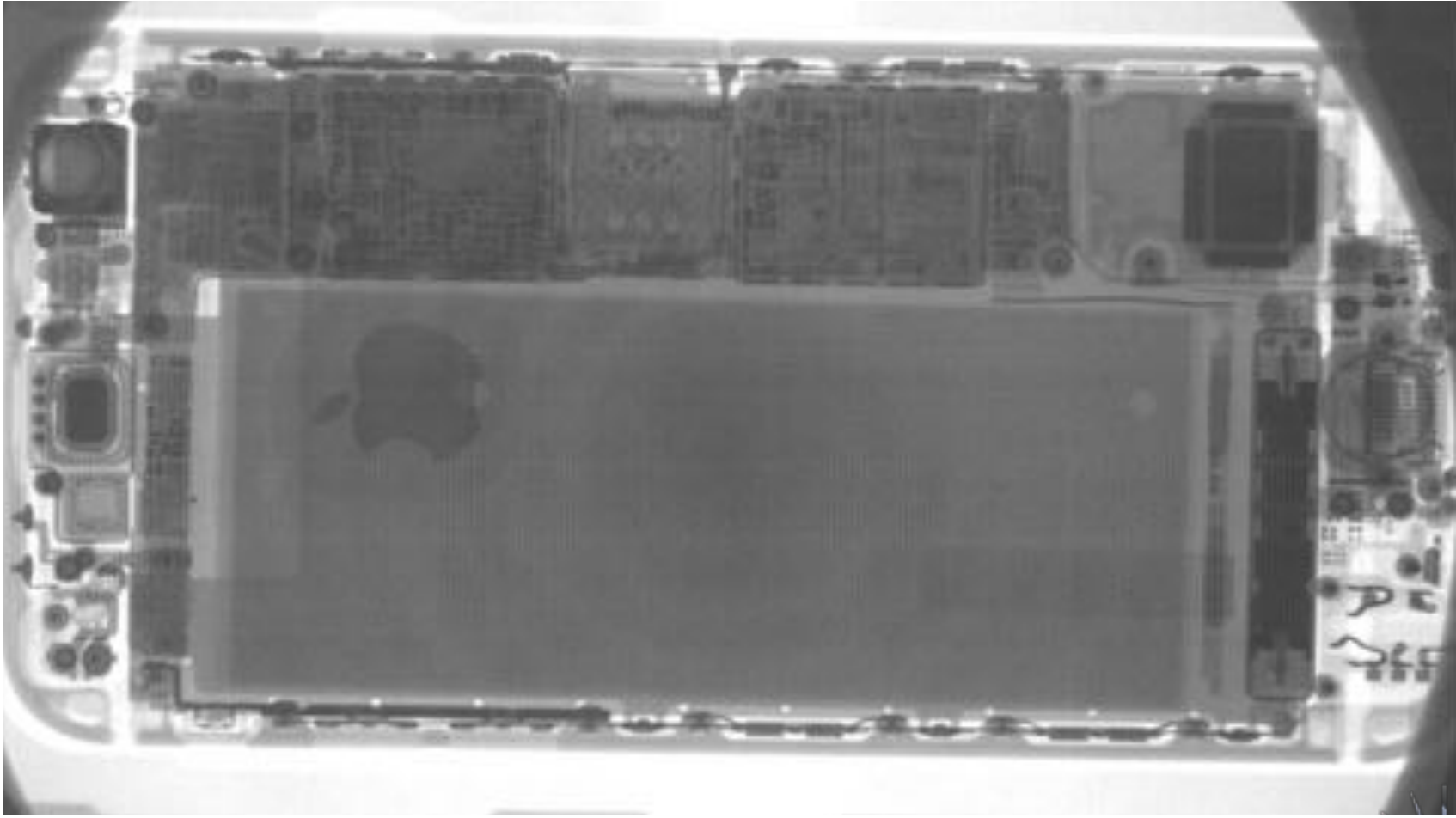


# Artificial Intelligence

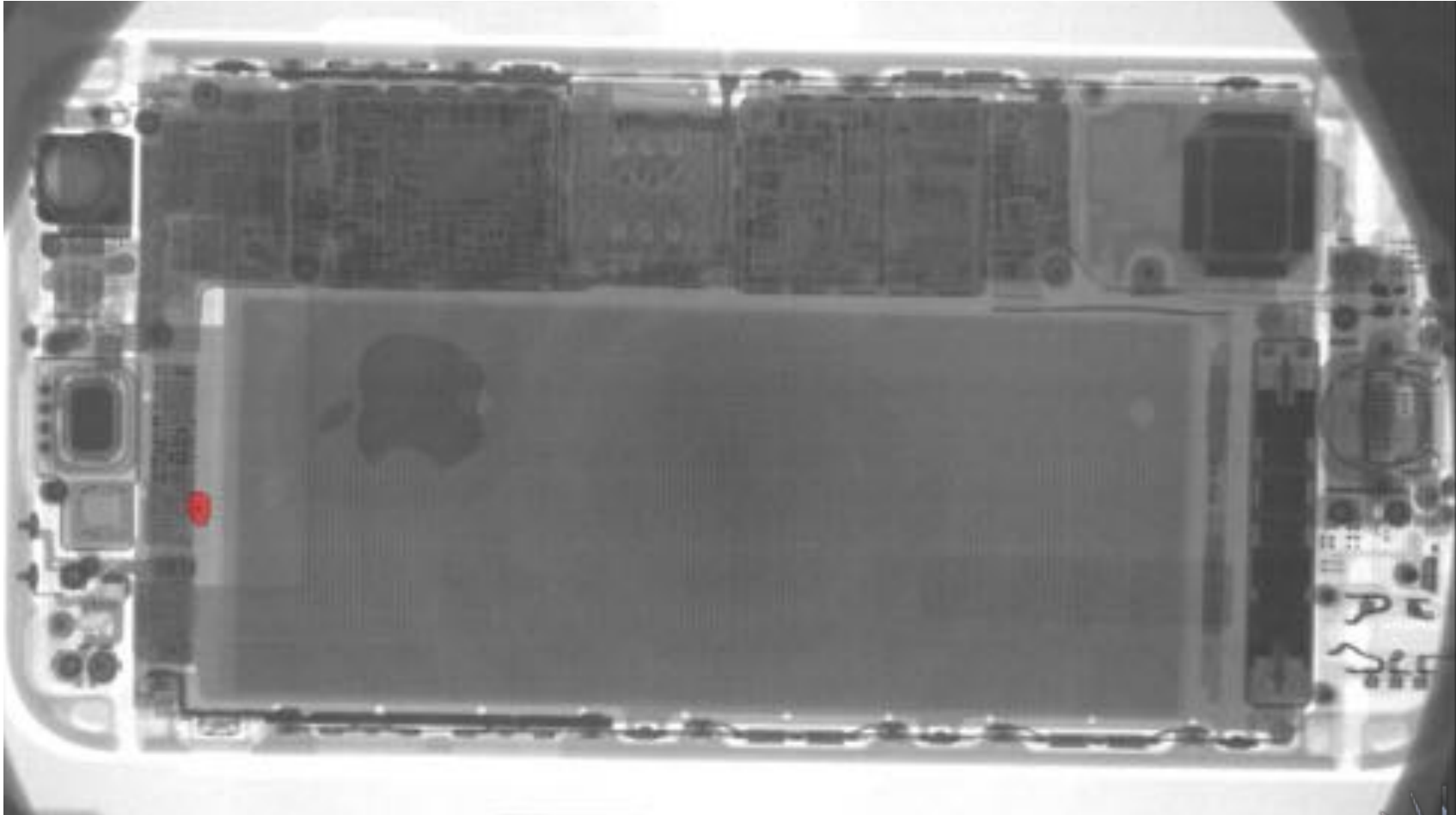
# 30-second intro to artificial intelligence (AI)

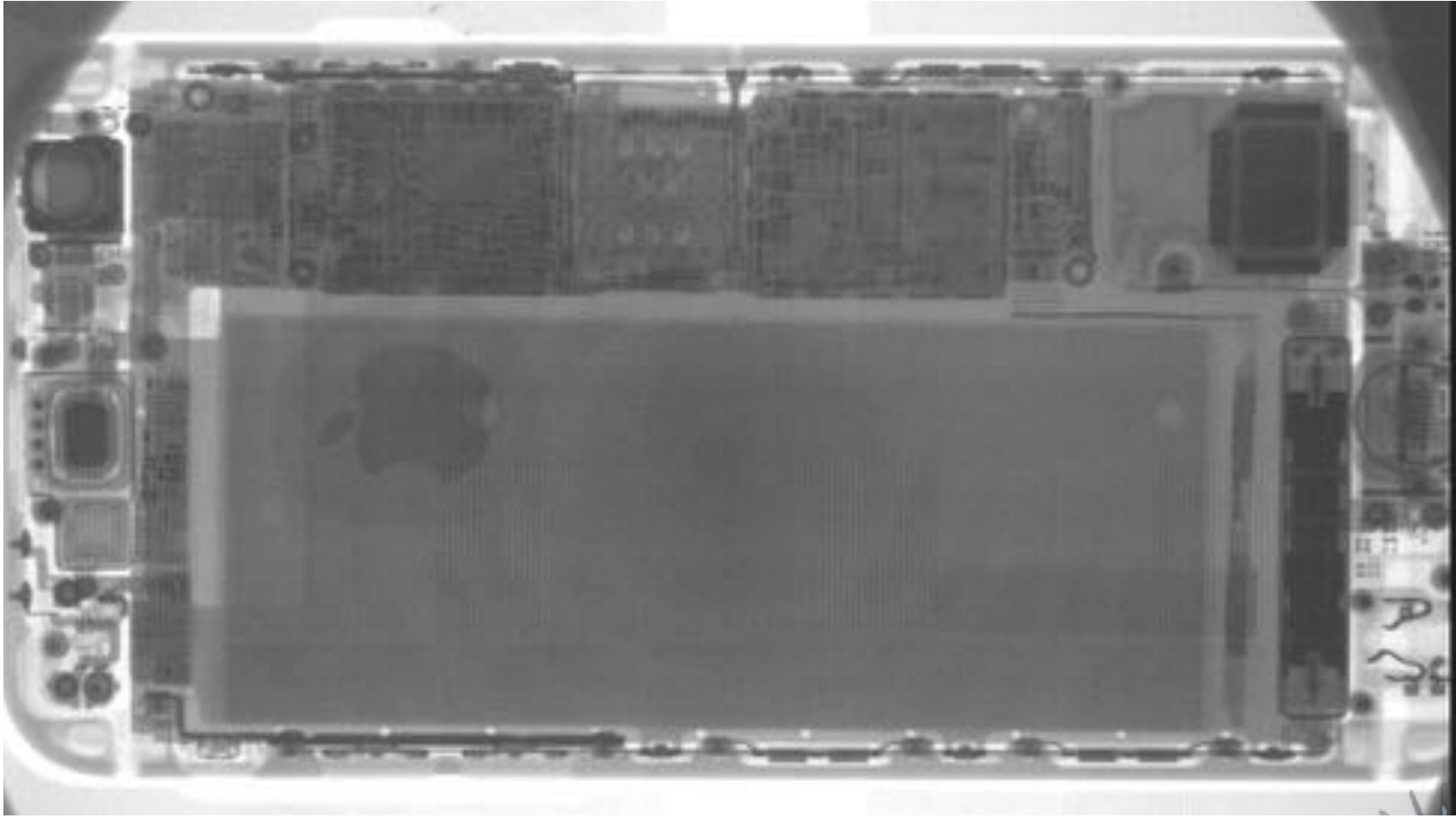


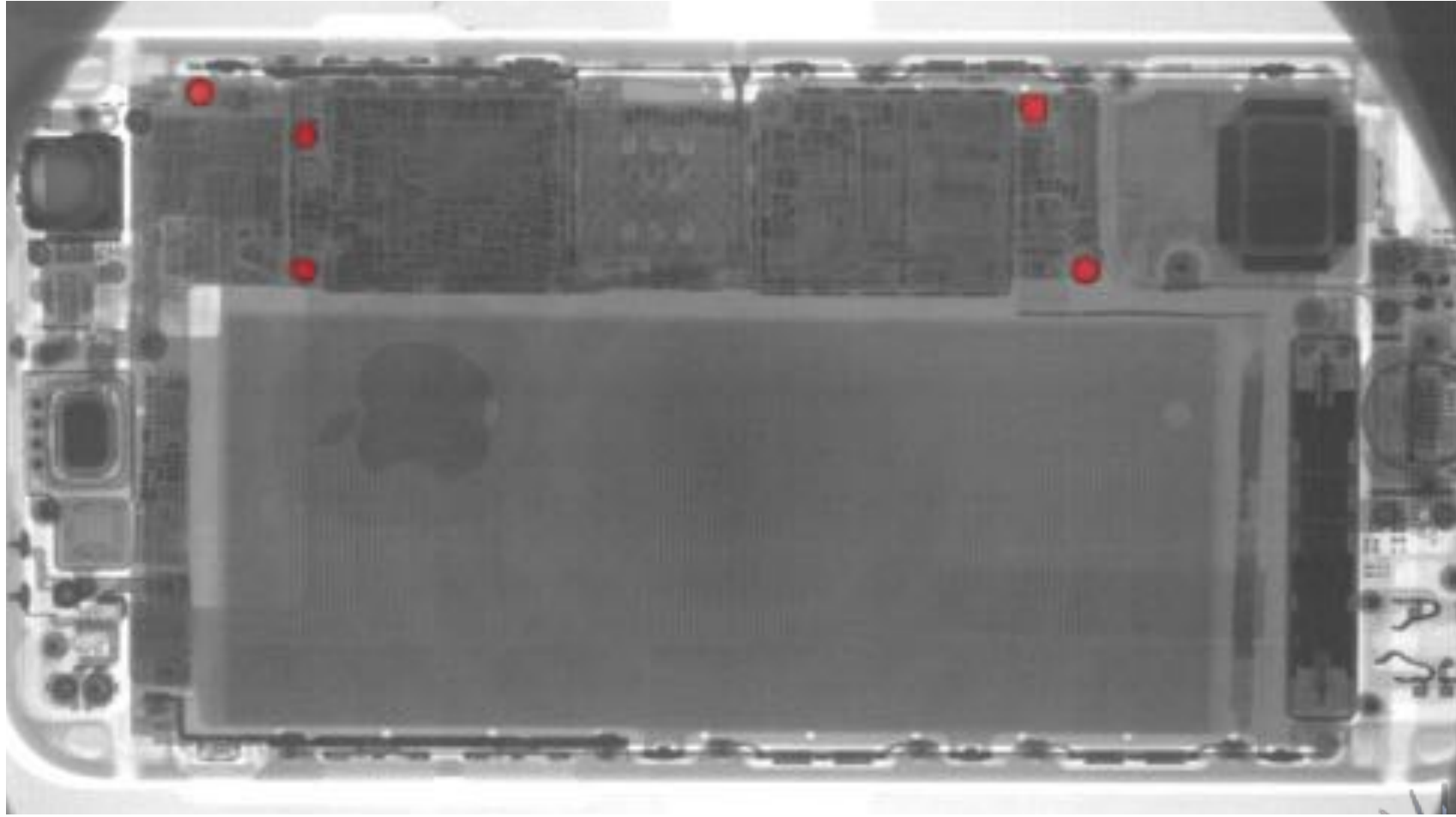
X	Y
2	4
0	0
3	6
-5	-10
10	20

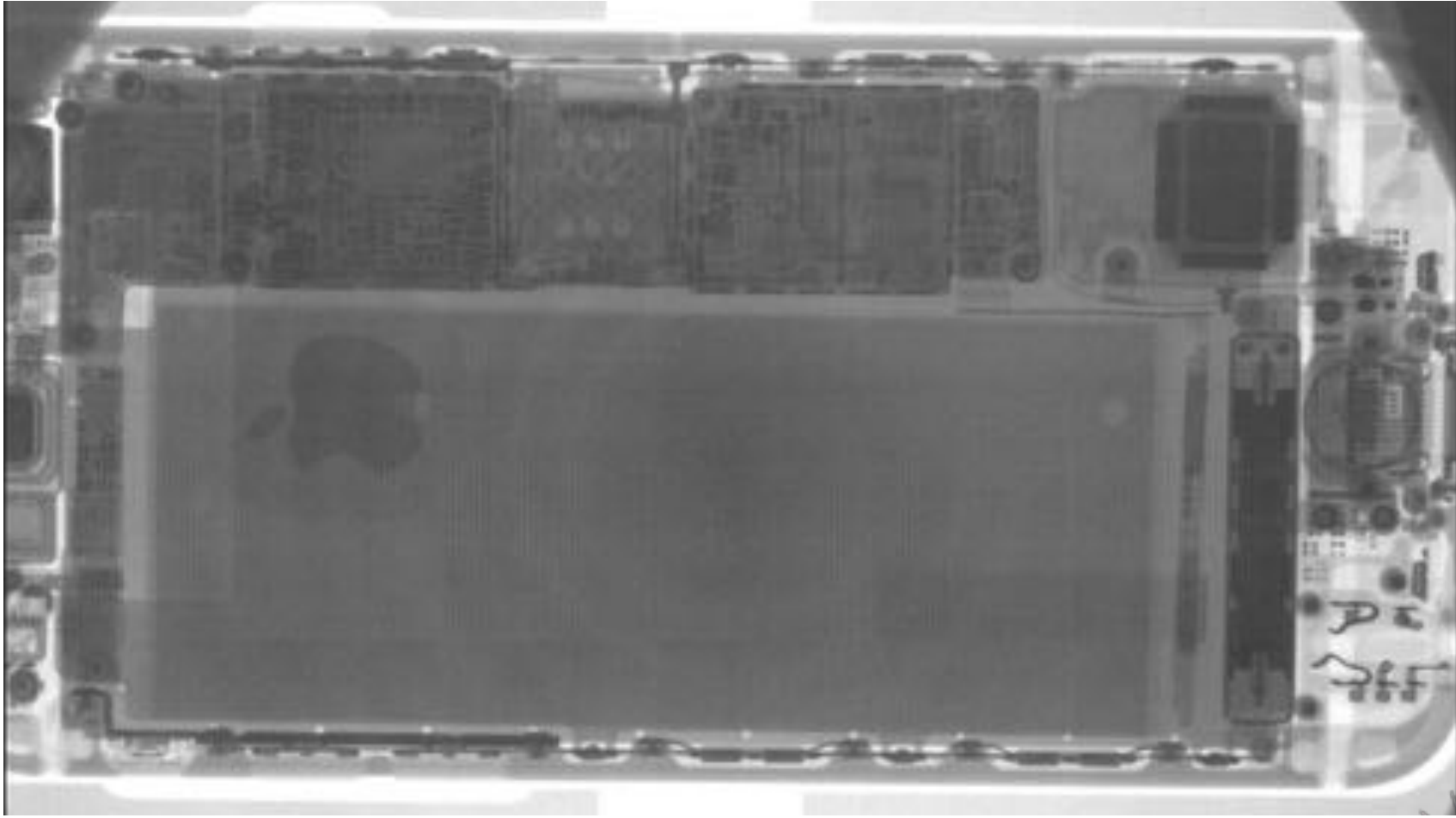
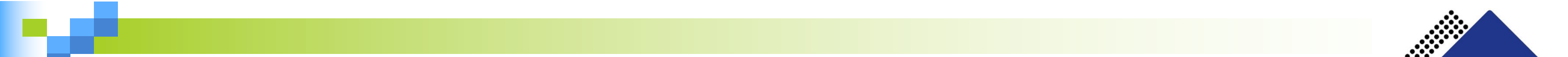


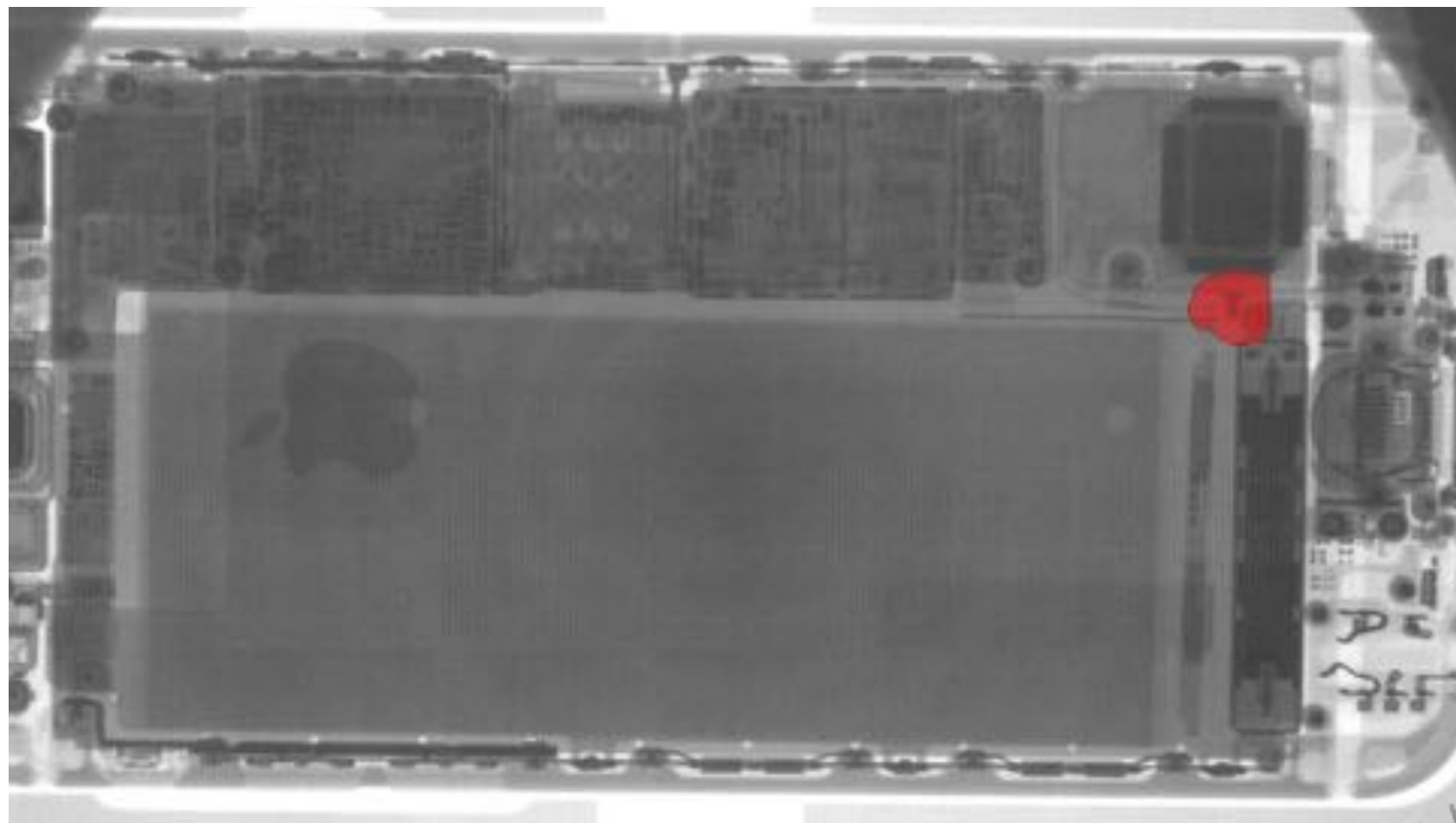




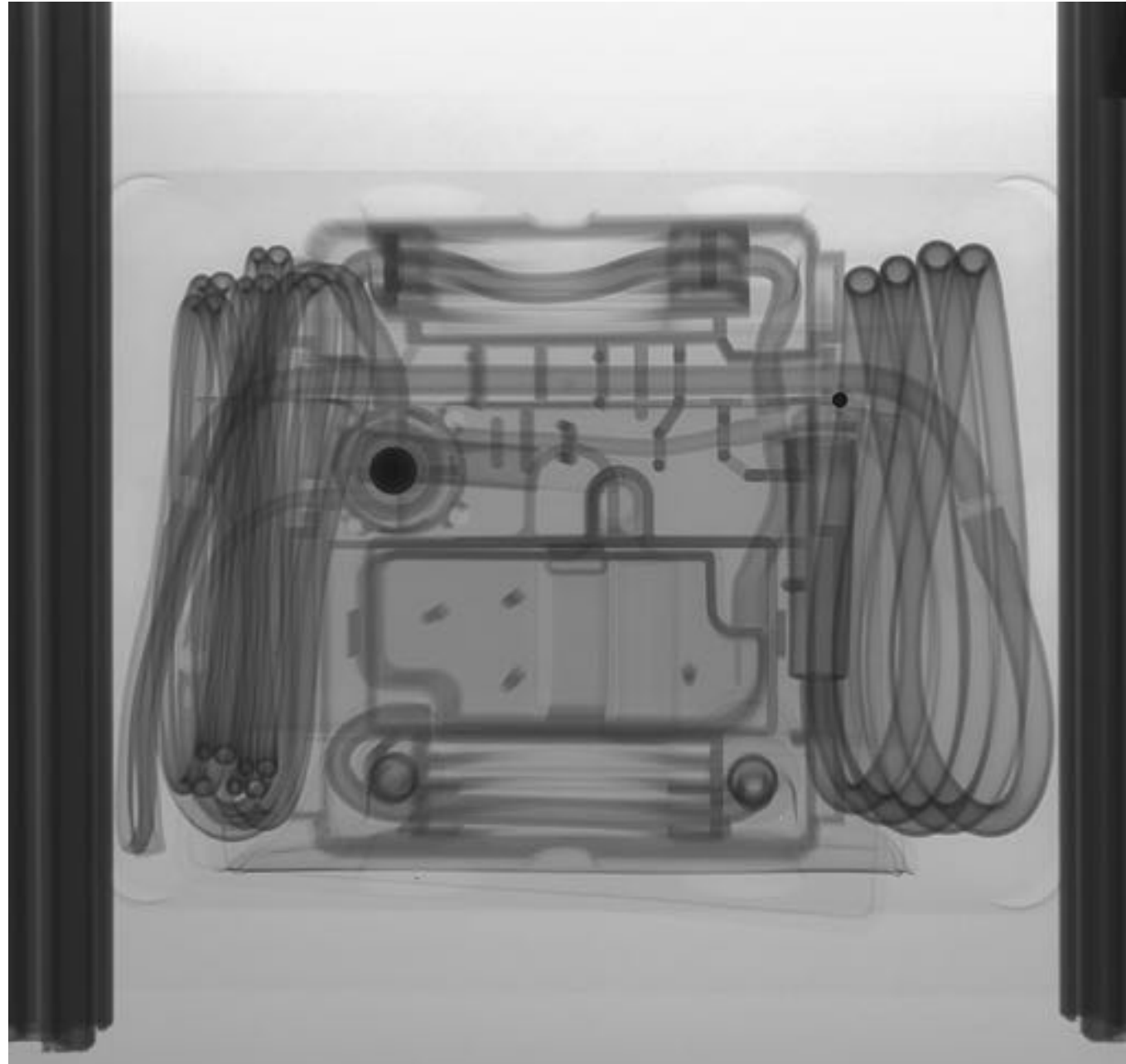


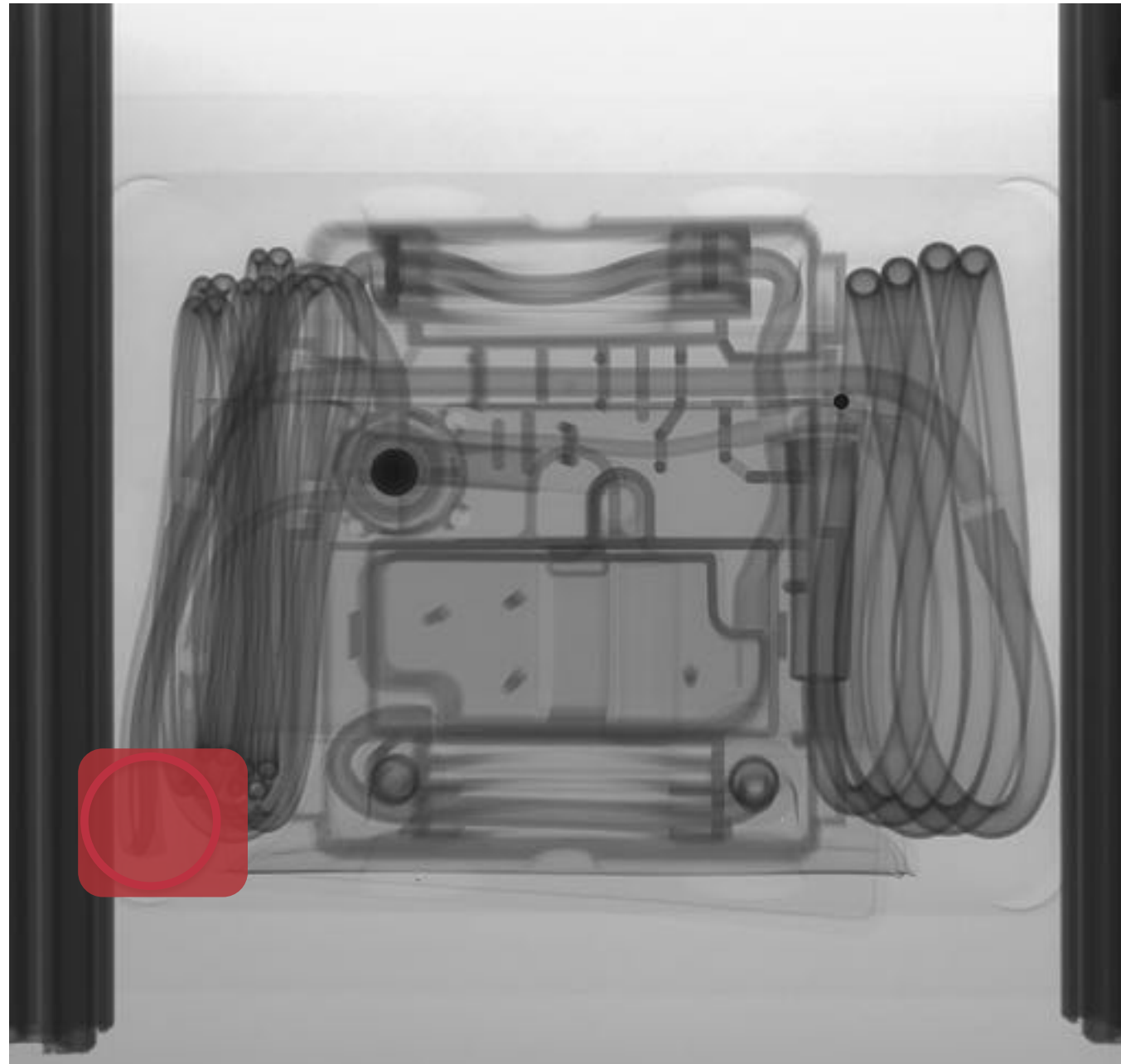












# Thanks for your time!



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